General Description

Note: Images are for illustrative purposes only; actual products may differ.

The BDE-SG1311R3 is a multiprotocol Sub-1GHz wireless module series based on Texas Instrument (TI)'s single-chip wireless microcontroller (MCU) CC1311R31T0RGZR. In order to fulfil different integration scenarios, BDE provides different variants for this module series. They are listed and described in Table 1.

The BDE-SG1311R3 module series is embeded with an powerful 48-MHz Arm® Cortex®-M4 processor which supports IEEE 802.15.4, IPv6-enabled smart objects (6LoWPAN), mioty, proprietary systems, including TI 15.4-Stack (Sub-1GHz). The module series is optimized for low-power wireless communication and advanced sensing in grid infrastructure, building automation, retail automation, personal electronics and medical applications.

The BDE-SG1311R3 has a low sleep current of 0.7 µA with RTC and 32KB RAM retention, which enables longer battery life wireless applications. The module supports +14 dBm output power with best-in-class transmit current consumption at 24.9 mA for Sub-1GHz operation. This is suitable for the long-range and low-power applications. The device also has an autonomous ultra-low power Sensor Controller CPU with fast wake-up capability.

The module series has a software defined radio powered by an Arm® Cortex® M0 which allows support for multiple physical layers and RF standards.

The module series integrates all required system-level hardware components including clocks, balun filter, other passives, and PCB trace antenna or U.FL connector into a small PCB form factor. It is for easy assembly and low-cost PCB design.

The module is pre-certified with FCC, ISED, CE to make easy integration and fast time-to-market for customers.

Table 1. Module Variants

Orderable Part Number	Antenna Options	On-Board SPI Flash (Mbit)	Operating Temperature
BDE-SG1311R3U32	U.FL Connector	32	-40 °C to +85 °C
BDE-SG1311R3N32	ANT Pin		
BDE-SG1311R3U0	U.FL Connector	0	
BDE-SG1311R3N0	ANT Pin		
BDE-SG1311R3U32-IN	U.FL Connector	32	-40 °C to +105 °C
BDE-SG1311R3N32-IN	ANT Pin		
BDE-SG1311R3U0-IN	U.FL Connector	0	
BDE-SG1311R3N0-IN	ANT Pin		

Key Features

- **Wireless microcontroller**
  - Powerful 48-MHz Arm® Cortex®- M4 processor
  - 352 KB flash program memory
  - 32 KB ultra-low leakage SRAM
  - 8 KB of cache SRAM (Alternatively available as general-purpose RAM)
  - Programmable radio includes support for 2-(G)FSK, 4-(G)FSK, MSK, OOK, IEEE 802.15.4 PHY and MAC
  - Supports over-the-air upgrade (OTA)
- **Low power consumption**
  - MCU consumption:
    - 2.63 mA active mode, CoreMark®
    - 55 µA/MHz running CoreMark®
    - 0.7 µA standby mode, RTC, 32 KB RAM
    - 0.1 µA shutdown mode, wake-up on pin
  - Radio Consumption:
    - 5.4 mA RX at 868 MHz
    - 24.9 mA TX at +14 dBm at 868 MHz
- **Wireless protocol support**
  - Mioty
  - Wireless M-Bus
  - SimpleLink™ TI 15.4-stack
  - 6LoWPAN
  - Proprietary systems
- **High performance radio**
  - –120 dBm for 2.5 kbps long-range mode
  - –110 dBm at 50 kbps, 802.15.4, 868 MHz
  - Output power up to +14 dBm with temperature compensation
  - Down to 4 kHz receiver filter bandwidth
- **MCU peripherals**
  - Digital peripherals can be routed to any GPIO
  - Four 32-bit or eight 16-bit general-purpose timers
  - 12-bit SAR ADC, 200 kSample/s, 8 channels
  - 8-bit DAC
  - Analog comparator
  - UART, SSI, I^2C, I^2S
  - Real-time clock (RTC)
  - Integrated temperature and battery monitor
  - 30 GPIOs – none SPI flash versions
  - 26 GPIOs – SPI flash versions
- **Security enablers**
  - AES 128-bit cryptographic accelerator
  - True random number generator (TRNG)
  - Additional cryptography drivers available in Software Development Kit (SDK)
- **Operating range**
  - On-chip buck DC/DC converter
  - 1.8 V to 3.8 V single supply voltage
  - 2.3-V to 3.6-V single supply voltage (SPI flash variants)
  - -40 to +85°C
- **Antenna options**
  - U.FL connector for external antenna
  - ANT Pin for external antenna
- **On-board SPI Flash**
  - 32-Mbit, only available in SPI flash versions
- **Package**
  - Dimension: 22 mm x 15 mm x 2.15 mm
  - LCC-39
  - RoHS-compliant package
- **Regulatory compliance**
  - FCC ID: 2ABRU-SG13R
  - IC: 25657-SG13R
  - CE-RED

Applications

- 868, 902 to 928 MHz ISM and SRD systems with down to 4 kHz of receive bandwidth
- Building automation
  - Building security systems – motion detector, electronic smart lock, door and window sensor, garage door system, gateway
  - HVAC – thermostat, wireless environmental sensor, HVAC system controller, gateway
  - Fire safety system – smoke and heat detector, fire alarm control panel (FACP)
  - Video surveillance – IP network camera
  - Elevators and escalators – elevator main control panel for elevators and escalators
- Grid infrastructure
  - Grid communications – wireless communications and long-range sensor applications
  - Other alternative energy – energy harvesting, solar inverters
- Industrial transport – asset tracking
- Factory automation and control
- Medical
- Electronic point of sale (EPOS) – Electronic Shelf Label (ESL)
- Personal electronics
  - Connected peripherals – consumer wireless module
  - Home theater & entertainment – smart speakers, set-top box
  - Gaming
  - Wearables (non-medical)

Module Family

Table 2. Module Family

Product Type & Series Name	Orderable Part Number	Chipset & Core	On-chip Flash Size (KB)	On-chip SRAM Size (KB)	Connectivity	Antenna Options	On-Board SPI Flash (Mbit)	Operating Temperature (℃)	Size (mm)
Module BDE-SG13R	BDE-SG1314R10U32	CC1314R10 Cortex-M33	1024	296	Sub-1GHz Wireless M-Bus & mioty & Wi-SUN & Sidewalk	U.FL connector	32	-40 to +85	22 X 15 X 2.15
	BDE-SG1314R10N32					ANT pin			
	BDE-SG1314R10U0					U.FL connector	0		
	BDE-SG1314R10N0					ANT pin			
	BDE-SG1314R10U32-IN					U.FL connector	32	-40 to +105	
	BDE-SG1314R10N32-IN					ANT pin			
	BDE-SG1314R10U0-IN					U.FL connector	0		
	BDE-SG1314R10N0-IN					ANT pin			
	BDE-SG1312R7U32	CC1312R7 Cortex-M4F	704	152	Sub-1GHz Wireless M-Bus & mioty & Wi-SUN & Sidewalk	U.FL connector	32	-40 to +85	
	BDE-SG1312R7N32					ANT pin			
	BDE-SG1312R7U0					U.FL connector	0		
	BDE-SG1312R7N0					ANT pin			
	BDE-SG1312R7U32-IN					U.FL connector	32	-40 to +105	
	BDE-SG1312R7N32-IN					ANT pin			
	BDE-SG1312R7U0-IN					U.FL connector	0		
	BDE-SG1312R7N0-IN					ANT pin			
	BDE-SG1312RU32	CC1312R Cortex-M4F	352	88	Sub-1GHz Wireless M-Bus & mioty & Wi-SUN & Sidewalk	U.FL connector	32	40 to +85	
	BDE-SG1312RN32					ANT pin			
	BDE-SG1312RU0					U.FL connector	0		
	BDE-SG1312RN0					ANT pin			
	BDE-SG1312RU32-IN					U.FL connector	32	-40 to +105	
	BDE-SG1312RN32-IN					ANT pin			
	BDE-SG1312RU0-IN					U.FL connector	0		
	BDE-SG1312RN0-IN					ANT pin			
	BDE-SG1311R3U32	CC1311R3 Cortex-M4	352	40	Sub-1GHz Wireless M-Bus & mioty	U.FL connector	32	-40 to +85	
	BDE-SG1311R3N32					ANT pin			
	BDE-SG1311R3U0					U.FL connector	0		
	BDE-SG1311R3N0					ANT pin			
	BDE-SG1311R3U32-IN					U.FL connector	32	-40 to +105	
	BDE-SG1311R3N32-IN					ANT pin			
	BDE-SG1311R3U0-IN					U.FL connector	0		
	BDE-SG1311R3N0-IN					ANT pin			

Naming Convention

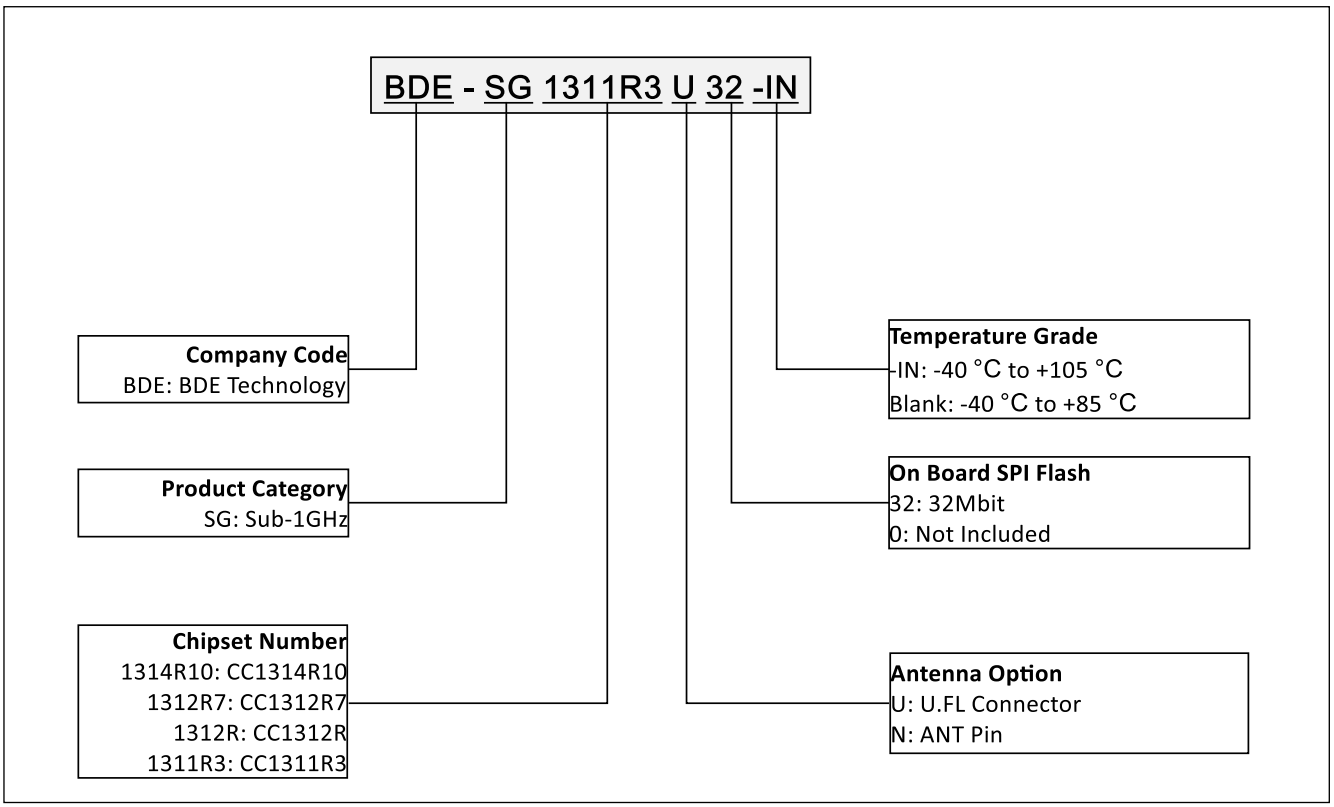


Figure 1. Module Naming Convention

Contents

List of Tables

List of Figures

References

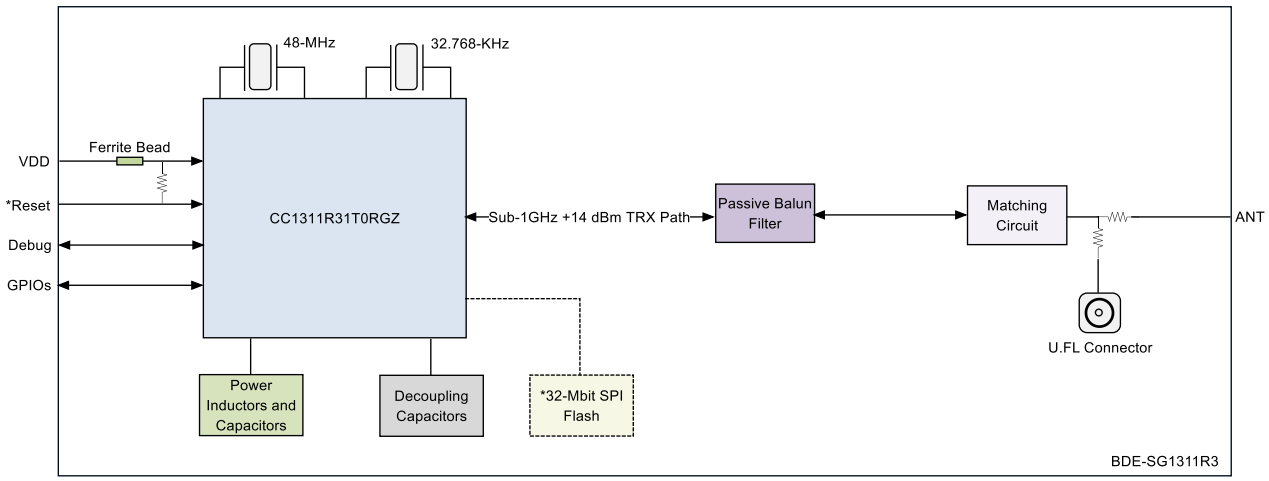
[1] CC1311R3 resources: https://www.ti.com/product/CC1311R3

1. System Overview

1.1. Block Diagram

BDE-SG1311R3 module series is based on the Texas Instruments' CC1311R3 single chip wireless MCU. The module integrates all required system-level hardware components including clocks, balun filter, other passives, and U.FL connector into a small PCB form factor.

The module, as seen in Figure 2, comprises of:
- 48-MHz XTAL
- 32.768-kHz XTAL
- Power inductors and capacitors
- Pull-up resistor
- Passive balun filter
- Decoupling capacitors
- Matching circuit
- ANT Pin (BDE-SG1311R3N)
- U.FL connector (BDE-SG1311R3U)



(1) The 32-Mbit SPI flash is only included in module BDE-SG1311R3x32 variants;
(2) Reset pin has an internal pull-up resistor and a decoupling capacitor.

Figure 2. BDE-SG1311R3 Module Block Diagram

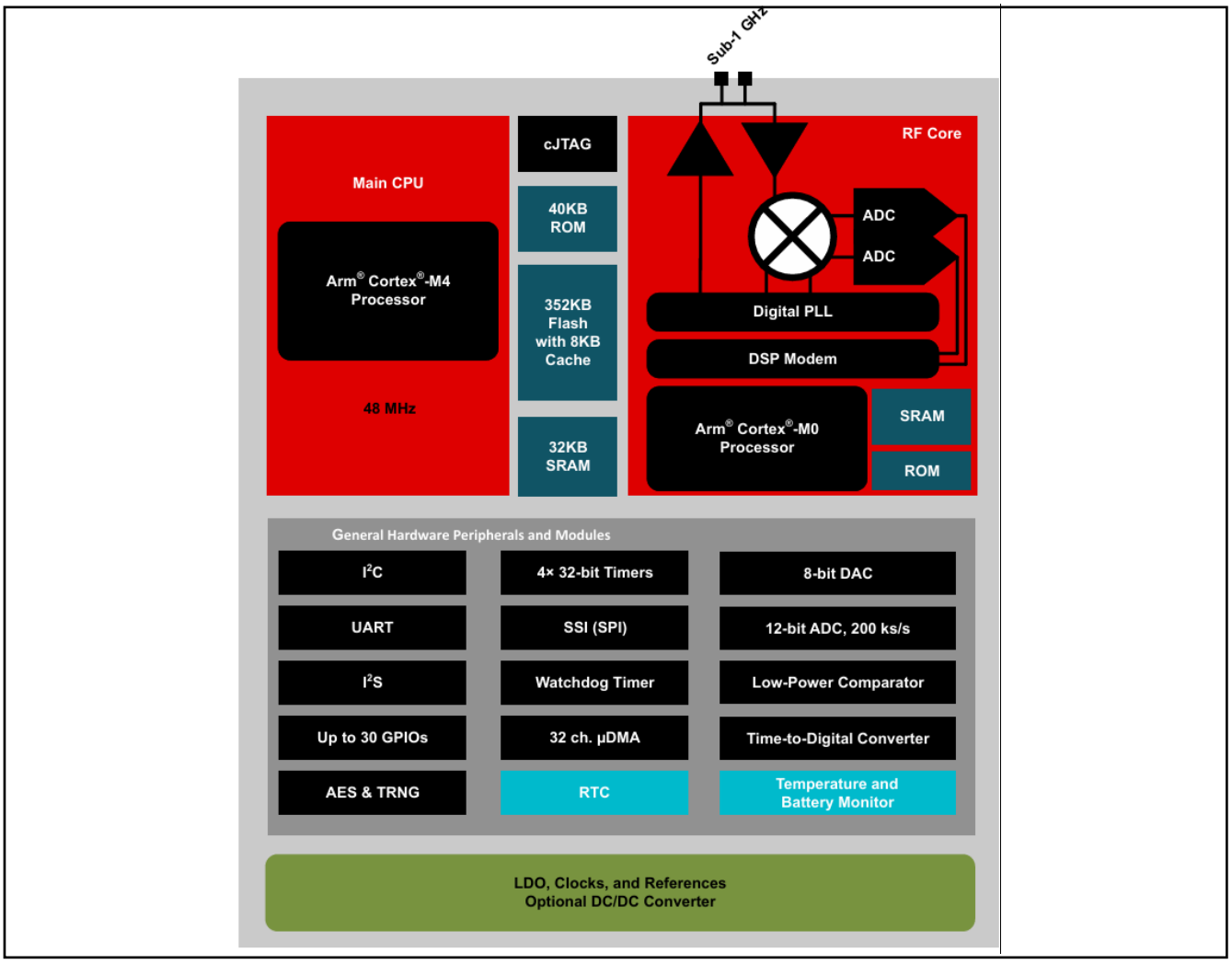


Figure 3. The Block Diagram of CC1311R3 (Adopted form CC1311R3 Datasheet)

1.2. System CPU

The BDE-SG1311R3 module series utilizes CC1311R3 SimpleLink™ Wireless MCU. The MCU contains an Arm® Cortex®-M4 system CPU, which runs the application and the higher layers of radio protocol stacks.

The system CPU is the foundation of a high-performance, low-cost platform that meets the system requirements of minimal memory implementation, and low-power consumption, while delivering outstanding computational performance and exceptional system response to interrupts.

1.3. Radio (RF Core)

The RF Core is a highly flexible and future proof radio module which contains an Arm Cortex-M0 processor that interfaces the analog RF and base-band circuitry, handles data to and from the system CPU side, and assembles the information bits in a given packet structure. The RF core offers a high level, command-based API to the main CPU that configurations and data are passed through. The Arm Cortex-M0 processor is not programmable by customers and is interfaced through the TI-provided RF driver that is included with the SimpleLink Software Development Kit (SDK).

The RF core can autonomously handle the time-critical aspects of the radio protocols, thus offloading the main CPU, which

reduces power and leaves more resources for the user application. Several signals are also available to control external circuitry such as RF switches or range extenders autonomously.

The various physical layer radio formats are partly built as a software defined radio where the radio behavior is either defined by radio ROM contents or by non-ROM radio formats delivered in form of firmware patches with the SimpleLink SDKs. This allows the radio platform to be updated for support of future versions of standards even with over-the-air (OTA) updates while still using the same silicon.

1.3.1. Proprietary Radio Formats

The BDE-SG1311R3 radio can support a wide range of physical radio formats through a set of hardware peripherals combined with firmware available in the device ROM, covering various customer needs for optimizing towards parameters such as speed or sensitivity. This allows great flexibility in tuning the radio both to work with legacy protocols as well as customizing the behavior for specific application needs.

Table 3 gives a simplified overview of features of the various radio formats available in ROM. Other radio formats may be available in the form of radio firmware patches or programs through the Software Development Kit (SDK) and may combine features in a different manner, as well as add other features.

Table 3. Feature Support

Feature	Main 2-(G)FSK Mode	High Data Rates	Low Data Rates	SimpleLink™ Long Range
Programmable preamble, sync word and CRC	Yes	Yes	Yes	No
Programmable receive bandwidth	Yes	Yes	Yes (down to 4 kHz)	Yes
Data / Symbol rate(3)	20 to 1000 kbps	≤ 2 Msps	≤ 100 ksps	≤ 20 ksps
Modulation format	2- (G)FSK	2-(G)FSK 4-(G)FSK	2-(G)FSK 4-(G)FSK	2- (G)FSK
Dual Sync Word	Yes	Yes	No	No
Carrier Sense (1) (2)	Yes	No	No	No
Preamble Detection(2)	Yes	Yes	Yes	No
Data Whitening	Yes	Yes	Yes	Yes
Digital RSSI	Yes	Yes	Yes	Yes
CRC filtering	Yes	Yes	Yes	Yes
Direct-sequence spread spectrum (DSSS)	No	No	No	1:2 1:4 1:8
Forward error correction (FEC)	No	No	No	Yes
Link Quality Indicator (LQI)	Yes	Yes	Yes	Yes

(1) Carrier Sense can be used to implement HW-controlled listen-before-talk (LBT) and Clear Channel Assessment (CCA) for compliance with such requirements in regulatory standards. This is available through the CMD_PROP_CS radio API.
(2) Carrier Sense and Preamble Detection can be used to implement sniff modes where the radio is duty cycled to save power.
(3) Data rates are only indicative. Data rates outside this range may also be supported. For some specific combinations of settings, a smaller range might be supported.

1.4. Memory

The up to 352 KB nonvolatile (Flash) memory provides storage for code and data. The flash memory is in-system programmable and erasable. The last flash memory sector must contain a Customer Configuration section (CCFG) that is used by boot ROM and TI provided drivers to configure the device. This configuration is done through the ccfg.c source file that is included in all TI provided examples.

The ultra-low leakage system static RAM (SRAM) is a single 32 kB block can be used for both storage of data and execution of code. Retention of SRAM contents in Standby power mode is enabled by default and included in Standby mode power consumption numbers.

To improve code execution speed and lower power when executing code from nonvolatile memory, a 4-way nonassociative 8 kB cache is enabled by default to cache and prefetch instructions read by the system CPU. The cache can be used as a general-purpose RAM by enabling this feature in the Customer Configuration Area (CCFG).

The ROM also contains a serial (SPI and UART) bootloader that can be used for initial programming of the device.

The module series also provides an option with integrated an on-board 32-Mbit SPI flash for the applications that need to store large application data.

1.5. Cryptography

The device comes with a wide set of modern cryptography-related hardware accelerators, drastically reducing code footprint and execution time for cryptographic operations. It also has the benefit of being lower power and improves availability and responsiveness of the system because the cryptography operations runs in a background hardware thread.

The hardware accelerator modules are:

- True Random Number Generator (TRNG) module provides a true, nondeterministic noise source for the purpose of generating keys, initialization vectors (IVs), and other random number requirements. The TRNG is built on 24 ring oscillators that create unpredictable output to feed a complex nonlinear-combinatorial circuit.
- Advanced Encryption Standard (AES) with 128 bit key lengths.

Together with the hardware accelerator module, a large selection of open-source cryptography libraries provided with the Software Development Kit (SDK), this allows for secure and future proof IoT applications to be easily built on top of the platform. The TI provided cryptography drivers are:

- Key Agreement Schemes
- Signature Generation
- Curve Support
- Hash
- MACs
- Block ciphers
- Authenticated Encryption
- Random number generation

1.6. Timers

A large selection of timers are available as part of the device. These timers are:

- Real-Time Clock (RTC)
- General Purpose Timers (GPTIMER)
- Radio Timer
- Watchdog timer

1.7. Serial Peripherals and I/O

The SSI is a synchronous serial interface that is compatible with SPI, MICROWIRE, and TI's synchronous serial interfaces. The SSI support both SPI master and slave up to 4 MHz. The SSI module support configurable phase and polarity.

The UART implement universal asynchronous receiver and transmitter functions. It support flexible baud-rate generation up to a maximum of 3 Mbps.

The I2S interface is used to handle digital audio and can also be used to interface pulse-density modulation microphones (PDM).

The I2C interface is also used to communicate with devices compatible with the I2C standard. The I2C interface can handle 100 kHz and 400 kHz operation, and can serve as both master and slave.

The I/O controller (IOC) controls the digital I/O pins and contains multiplexer circuitry to allow a set of peripherals to be assigned to I/O pins in a flexible manner. All digital I/Os are interrupt and wake-up capable, have a programmable pullup and pulldown function, and can generate an interrupt on a negative or positive edge (configurable). When configured as an output, pins can function as either push-pull or open-drain. Five GPIOs have high-drive capabilities, which are marked in bold in Section 2.1. All digital peripherals can be connected to any digital pin on the device.

1.8. Battery and Temperature Monitor

A combined temperature and battery voltage monitor is available in the device. The battery and temperature monitor allows an application to continuously monitor on-chip temperature and supply voltage and respond to changes in environmental conditions as needed. The module contains window comparators to interrupt the system CPU when temperature or supply voltage go outside defined windows. These events can also be used to wake up the device from Standby mode through the Always-On (AON) event fabric.

1.9. µDMA

The device includes a direct memory access (µDMA) controller. The µDMA controller provides a way to offload data-transfer tasks from the system CPU, thus allowing for more efficient use of the processor and the available bus bandwidth. The µDMA controller can perform a transfer between memory and peripherals. The µDMA controller has dedicated channels for each supported on-chip module and can be programmed to automatically perform transfers between peripherals and memory when the peripheral is ready to transfer more data.

1.10. Debug

The on-chip debug support is done through a dedicated cJTAG (IEEE 1149.7) or JTAG (IEEE 1149.1) interface. The device boots by default into cJTAG mode and must be reconfigured to use 4-pin JTAG.

1.11. Clock Systems

The module has several internal system clocks.

The 48 MHz SCLK_HF is used as the main system (MCU and peripherals) clock. This can be driven by the internal 48 MHz RC Oscillator (RCOSC_HF) or an external 48 MHz crystal (XOSC_HF). Radio operation requires an external 48 MHz crystal.

SCLK_LF is the 32.768 kHz internal low-frequency system clock. It can be used by the Sensor Controller for ultra-low-power operation and is also used for the RTC and to synchronize the radio timer before or after Standby power mode. SCLK_LF can be driven by the internal 32.8 kHz RC Oscillator (RCOSC_LF), a 32.768 kHz watch-type crystal, or a clock input on any digital IO.

When using a crystal or the internal RC oscillator, the device can output the 32 kHz SCLK_LF signal to other devices, thereby reducing the overall system cost.

The module includes two crystals on board, a high frequency crystal (HFXT) with 48-MHz and a low frequency crystal (LFXT) with 32.768-KHz.

1.12. Network Processor

Depending on the product configuration, the device can function as a wireless network processor (WNP - a device running the wireless protocol stack with the application running on a separate host MCU), or as a system-on-chip (SoC) with the application and protocol stack running on the system CPU inside the device.

In the first case, the external host MCU communicates with the device using SPI or UART. In the second case, the application must be written according to the application framework supplied with the wireless protocol stack.

1.13. Power Management

To minimize power consumption, the BDE-SG1311R3 series supports a number of power modes and power management features (see Table 4).

Table 4. Power Modes

Mode	Software Configurable Power Modes				Reset Pin Held
	Active	Idle	Standby	Shutdown	
CPU	Active	Off	Off	Off	Off
Flash	On	Available	Off	Off	Off
SRAM	On	On	Retention	Off	Off
Supply System	On	On	Duty Cycled	Off	Off
Register and CPU retention	Full	Full	Partial	No	No
SRAM retention	Full	Full	Full	No	No

Mode	Software Configurable Power Modes				Reset Pin Held
	Active	Idle	Standby	Shutdown	
48 MHz high-speed clock (SCLK_HF)	XOSC_HF or RCOSC_HF	XOSC_HF or RCOSC_HF	Off	Off	Off
32 kHz low-speed clock (SCLK_LF)	XOSC_LF or RCOSC_LF	XOSC_LF or RCOSC_LF	XOSC_LF or RCOSC_LF	Off	Off
Peripherals	Available	Available	Off	Off	Off
Wake-up on RTC	Available	Available	Available	Off	Off
Wake-up on pin edge	Available	Available	Available	Available	Off
Wake-up on reset pin	On	On	On	On	On
Brownout detector (BOD)	On	On	Duty Cycled	Off	Off
Power-on reset (POR)	On	On	On	Off	Off
Watchdog timer (WDT)	Available	Available	Paused	Off	Off

In Active mode, the application system CPU is actively executing code. Active mode provides normal operation of the processor and all of the peripherals that are currently enabled. The system clock can be any available clock source (see Table 4).

In Idle mode, all active peripherals can be clocked, but the Application CPU core and memory are not clocked and no code is executed. Any interrupt event brings the processor back into active mode.

In Standby mode, only the always-on (AON) domain is active. An external wake-up event, RTC event, or Sensor Controller event is required to bring the device back to active mode. MCU peripherals with retention do not need to be reconfigured when waking up again, and the CPU continues execution from where it went into standby mode. All GPIOs are latched in standby mode.

In Shutdown mode, the device is entirely turned off (including the AON domain and Sensor Controller), and the I/Os are latched with the value they had before entering shutdown mode. A change of state on any I/O pin defined as a wake from shutdown pin wakes up the device and functions as a reset trigger. The CPU can differentiate between reset in this way and reset-by-reset pin or power-on reset by reading the reset status register. The only state retained in this mode is the latched I/O state and the flash memory contents.

The power, RF and clock management for the CC1311R3 device require specific configuration and handling by software for optimized performance. This configuration and handling is implemented in the TI-provided drivers that are part of the CC1311R3 software development kit (SDK). Therefore, TI highly recommends using this software framework for all application development on the device. The complete SDK with TI-RTOS (optional), device drivers, and examples is offered free of charge in source code.

1.14. Antenna

The module series provides two options for connecting external antenna, integrated U.FL connector and ANT pin. Refer to Section 7.1.1 for certified antenna list.

2. Pinout Functions

The module series is with LCC-39 package, 39 pads are exposed for user. This section describes pinout functions of the module in details.

2.1. Pin Diagram

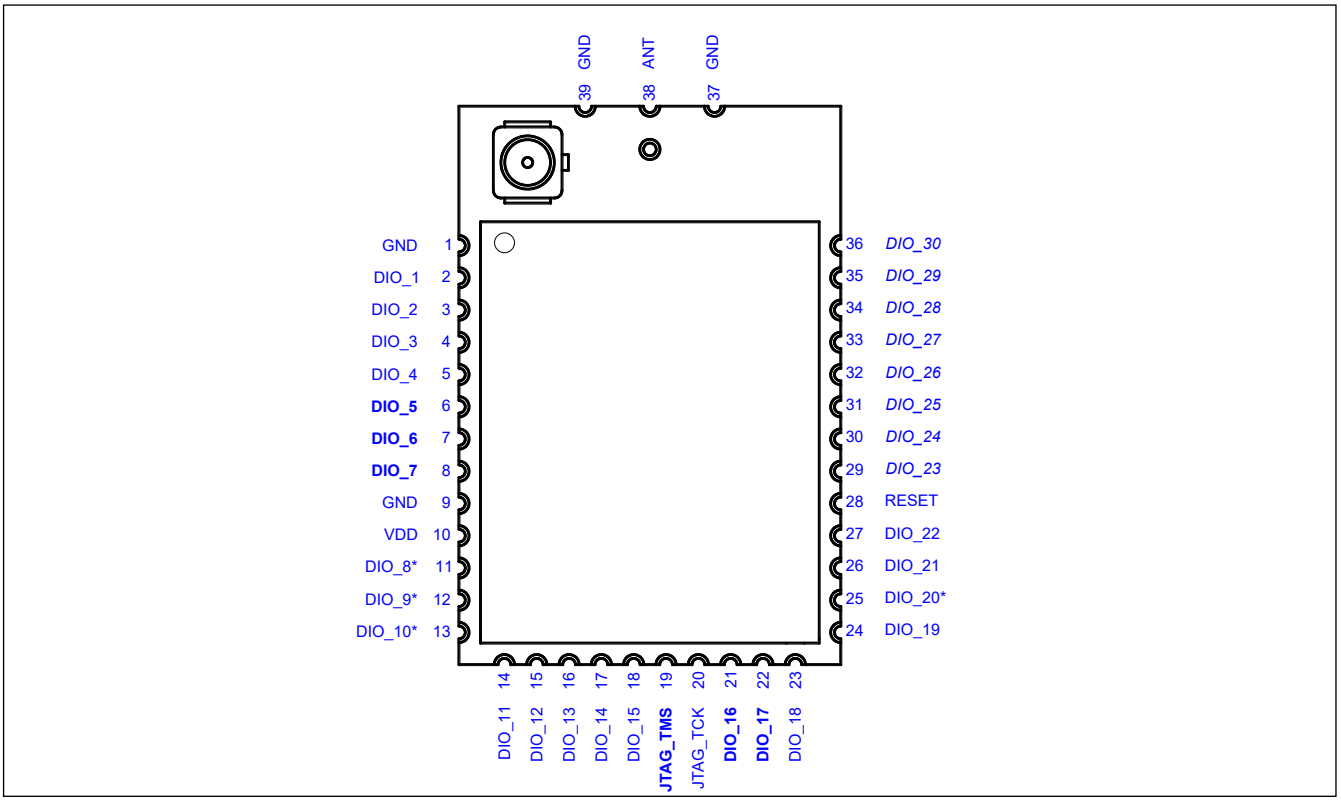


Figure 4. Pin Diagram of BDE-SG1311R3 (Top View)

The following I/O pins marked in **bold** in Figure 4 have high-drive capabilities:

- Pin 6, DIO_5
- Pin 7, DIO_6
- Pin 8, DIO_7
- Pin 19, JTAG_TMSC
- Pin 21, DIO_16
- Pin 22, DIO_17

The following I/O pins marked in *italics* in Figure 4 have analog capabilities:

- Pin 29, DIO_23
- Pin 30, DIO_24
- Pin 31, DIO_25
- Pin 32, DIO_26
- Pin 33, DIO_27
- Pin 34, DIO_28

- Pin 35, DIO_29
- Pin 36, DIO_30

The following four I/O pins are assigned to on-board 32-Mbit SPI flash for SPI flash variants:

- Pin 11, SFL_MISO_DIO_8
- Pin 12, SFL_MOSI_DIO_9
- Pin 13, SFL_CLK_DIO_10
- Pin 25, SFL_CS_DIO_20

2.2. Pin Attributes and Pin Multiplexing

Table 5 describes the definitions of the pins of the module.

Table 5. Pinout Description

Module Pin #	Pin Name	Type	CC1311R31T0RGZR Pin #	Description
1	GND	Ground	-	Power ground
2	DIO_1	I/O	6	GPIO, Sensor Controller
3	DIO_2	I/O	7	GPIO, Sensor Controller
4	DIO_3	I/O	8	GPIO, Sensor Controller
5	DIO_4	I/O	9	GPIO, Sensor Controller
6	DIO_5	I/O	10	GPIO, Sensor Controller, high-drive capability
7	DIO_6	I/O	11	GPIO, Sensor Controller, high-drive capability
8	DIO_7	I/O	12	GPIO, Sensor Controller, high-drive capability
9	GND	Ground	-	Power ground
10	VDD	Power	-	Power supply
11	DIO_8 (2)	I/O	14	GPIO, assigned as SPI_MISO of on-module SPI flash in BDE-SG1311R3X32
12	DIO_9 (2)	I/O	15	GPIO, assigned as SPI_MOSI of on-module SPI flash in BDE-SG1311R3X32
13	DIO_10 (2)	I/O	16	GPIO, assigned as SPI_SCLK of on-module SPI flash in BDE- SG1311R3X32
14	DIO_11	I/O	17	GPIO
15	DIO_12	I/O	18	GPIO
16	DIO_13	I/O	19	GPIO
17	DIO_14	I/O	20	GPIO
18	DIO_15	I/O	21	GPIO
19	JTAG_TMS	I/O	24	JTAG TMSC, high-drive capability
20	JTAG_TCK	I	25	JTAG TCKC
21	DIO_16	I/O	26	GPIO, JTAG_TDO, high-drive capability
22	DIO_17	I/O	27	GPIO, JTAG_TDI, high-drive capability
23	DIO_18	I/O	28	GPIO
24	DIO_19	I/O	29	GPIO
25	DIO_20 (2)	I/O	30	GPIO, assigned as SPI_CS of on-module SPI flash in BDE-SG1311R3X32
26	DIO_21	I/O	31	GPIO
27	DIO_22	I/O	32	GPIO

Module Pin #	Pin Name	Type	CC1311R31T0RGZR Pin #	Description
28	RESET	I	35	Reset, active-low, 100K ohm internal pull-up resistor
29	DIO_23	I/O	36	GPIO, Sensor Controller, analog capability
30	DIO_24	I/O	37	GPIO, Sensor Controller, analog capability
31	DIO_25	I/O	38	GPIO, Sensor Controller, analog capability
32	DIO_26	I/O	39	GPIO, Sensor Controller, analog capability
33	DIO_27	I/O	40	GPIO, Sensor Controller, analog capability
34	DIO_28	I/O	41	GPIO, Sensor Controller, analog capability
35	DIO_29	I/O	42	GPIO, Sensor Controller, analog capability
36	DIO_30	I/O	43	GPIO, Sensor Controller, analog capability
37	GND	Ground	-	Power ground
38	ANT	-	-	Antenna port (When disconnected with UFL, this port can be used)
39	GND	Ground	-	Power ground

(1) For pin multiplexing details, refer to CC1311R3 SimpleLink™ Arm® Cortex®-M4 Sub-1GHz wireless MCU with 352 kB flash;
(2) These four pins are assigned as SPI for on-board 32-Mbit flash in SPI flash variants modules and are not exposed for user;
(3) For operating voltage, please refer to Table 9.

2.3. Connections for Unused Pins

Table 6. Connections for Unused Pins

Function	Signal Name	Acceptable Practice	Proffered Practice
GPIO (Digital or analog)	DIOn	NC or GND	NC

3. Specifications

3.1. Electrical Characteristics

3.1.1. Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Over operating free-air temperature range (unless otherwise noted).

Table 7. Absolute Maximum Ratings

Parameter	MIN	MAX	Unit	Notes
VDD	-0.3	4.1	V	
Voltage on any digital pins	-0.3	VDD+0.3≤4.1	V	
Voltage on ADC input	-0.3	VDDS	V	Voltage scaling enabled
	-0.3	1.49	V	Voltage scaling disabled, internal reference
	-0.3	VDD/2.9	V	Voltage scaling disabled, VDD as reference
Storage temperature	-40	125	°C	

3.1.2. ESD Ratings

Table 8. ESD Ratings

Parameter	Description	Value	Unit	Note
Electrostatic discharge	Contact discharge	4000	V	As per EN 301-489
	Air discharge	8000	V	As per EN 301-489

3.1.3. Recommended Operating Conditions

Operation at or near maximum operating temperature for extended durations will result in a reduction in lifetime.

Over operating free-air temperature range (unless otherwise noted).

Table 9. Recommended Operating Conditions

Parameter	MIN	TYP	MAX	UNIT
VDD	1.8	3.3	3.8	V
VDD (For SPI flash variants)	2.3	3.3	3.8	V
Operating temperature	-40	-	85	°C
Operating temperature (-IN variants)	-40	-	105	°C
Rising supply voltage slew rate	0		100	mV/us
Falling supply voltage slew rate	0		20	mV/us

3.1.4. Power Consumption

The measurement is made with the evaluation module (EM board) for BDE-SG1311R3 with T_A = 25 °C, VDD = 3.0 V, DCDC enabled, GLDO disabled, unless otherwise noted.

Table 10. Power Consumption – Power Modes

Power Mode	Test Condition	TYP	Unit
Reset	Reset. RESET pin asserted or VDD below power-on-reset threshold	115	nA
Shutdown	Shutdown. No clocks running, no retention	115	nA
Standby without cache retention	RTC running, CPU, 32 kB RAM and (partial) register retention. RCOSC_LF	0.7	uA
	RTC running, CPU, 32 kB RAM and (partial) register retention. XOSC_LF	0.8	uA
Standby with cache retention	RTC running, CPU, 32 kB RAM and (partial) register retention. RCOSC_LF	2.1	uA
	RTC running, CPU, 32 kB RAM and (partial) register retention. XOSC_LF	2.2	uA
Idle	Supply Systems and RAM powered RCOSC_HF	570	uA
Active	MCU running CoreMark at 48 MHz RCOSC_HF	2.5	mA
Peripheral, power domain	Delta current with domain enabled	47	uA
Peripheral, Serial power domain	Delta current with domain enabled	3.3	uA
Peripheral, RF Core	Delta current with power domain enabled, clock enabled, RF core idle	122	uA
Peripheral, µDMA	Delta current with clock enabled, module is idle	58.1	uA
Peripheral, Timers	Delta current with clock enabled, module is idle	87	uA
Peripheral, I2C	Delta current with clock enabled, module is idle	11.6	uA
Peripheral, I2S	Delta current with clock enabled, module is idle	25.8	uA
Peripheral, SPI	Delta current with clock enabled, module is idle	61.3	uA
Peripheral, UART	Delta current with clock enabled, module is idle	125	uA
Peripheral, CRYPTO (AES)	Delta current with clock enabled, module is idle	25.2	uA
Peripheral, TRNG	Delta current with clock enabled, module is idle	23.3	uA

Table 11. Power Consumption – Radio Modes

Power Mode	Test Condition	TYP	Unit
Radio receive current	868 MHz	5.4	mA
Radio transmit current	0 dBm output power setting 868 MHz	7.4	mA
	+10 dBm output power setting 868 MHz	13.9	mA
	+14 dBm output power setting 868 MHz	24.9	mA

3.1.5. Clock Characteristics

Table 12. 48-MHz Crystal Oscillator (XOSC_HF) Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Crystal frequency			48		MHz
ESR, Equivalent series resistance					Ω
Frequency tolerance	T_A: 25°C	-10		+10	ppm
Frequency stability	T_A: -40°C ~ 85°C	-30		+30	ppm
C_L, Crystal load capacitance			7		pF

Table 13. 32.768-KHz Crystal Oscillator (XOSC_LF) Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Crystal frequency			32.768		KHz
ESR, Equivalent series resistance					Ω
Frequency tolerance	T_A: 25°C	-20		+20	ppm
Frequency stability	T_A: -40°C ~ 85°C	-30		+30	ppm
C_L, Crystal load capacitance			12.5		pF

3.1.6. Reset Timing

Table 14. Reset Timing

Parameter	MIN	TYP	MAX	Unit
nRESET low duration	1			us

3.1.7. UART Characteristics

Measured over operating free-air temperature range (unless otherwise noted)

Table 15. UART Characteristics

Parameter	MIN	TYP	MAX	Unit
UART baud rate			3	MBaud

3.1.8. SSI Characteristics

Measured over operating free-air temperature range (unless otherwise noted)

Table 16. SSI Characteristics

Parameter		MIN	TYP	MAX	Unit
T_{clk_per}	SSIClk cycle time	12		65024	System Clock
T_{clk_high}	SSIClk high time		0.5		T_{clk_per}
T_{clk_low}	SSIClk low time		0.5		T_{clk_per}

For SSI characteristics or other details, please refer to CC1311R3 datasheet: CC1311R3 SimpleLink™ Arm® Cortex®-M4 Sub-1GHz wireless MCU with 352 kB flash

3.1.9. GPIO DC Characteristics

Table 17. GPIO DC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
T_A = 25 °C, V_{DD} = 1.8 V					
GPIO VOH at 8 mA load	IOCURR = 2, high-drive GPIOs only		1.56		V
GPIO VOL at 8 mA load	IOCURR = 2, high-drive GPIOs only		0.24		V
GPIO VOH at 4 mA load	IOCURR = 1		1.59		V
GPIO VOL at 4 mA load	IOCURR = 1		0.21		V
GPIO pullup current	Input mode, pullup enabled, Vpad = 0 V		73		µA
GPIO pulldown current	Input mode, pulldown enabled, Vpad = VDD		19		µA
GPIO low-to-high input	IH = 1, transition voltage for input read as 0 → 1		1.08		V

transition, with hysteresis					
GPIO high-to-low input transition, with hysteresis	IH = 1, transition voltage for input read as 1 → 0		0.73		V
GPIO input hysteresis	IH = 1, difference between 0 → 1 and 1 → 0 points		0.35		V
T_A = 25 °C, V_{DD} = 3.0 V					
GPIO VOH at 8 mA load	IOCURR = 2, high-drive GPIOs only		2.59		V
GPIO VOL at 8 mA load	IOCURR = 2, high-drive GPIOs only		0.42		V
GPIO VOH at 4 mA load	IOCURR = 1		2.63		V
GPIO VOL at 4 mA load	IOCURR = 1		0.40		V
T_A = 25 °C, V_{DD} = 3.8 V					
GPIO pullup current	Input mode, pullup enabled, Vpad = 0 V		282		µA
GPIO pulldown current	Input mode, pulldown enabled, Vpad = VDD		110		µA
GPIO low-to-high input transition, with hysteresis	IH = 1, transition voltage for input read as 0 → 1		1.97		V
GPIO high-to-low input transition, with hysteresis	IH = 1, transition voltage for input read as 1 → 0		1.55		V
GPIO input hysteresis	IH = 1, difference between 0 → 1 and 1 → 0 points		0.42		V
T_A = 25 °C					
VIH	Lowest GPIO input voltage reliably interpreted as a High	0.8*VDD			V
VIL	Highest GPIO input voltage reliably interpreted as a Low			0.2*VDD	V

3.1.10. ADC Characteristics

Table 18. ADC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Input voltage range		0		VDD	V
Resolution			12		Bits
Sample Rate				200	ksps
Offset	Internal 4.3V equivalent reference		-0.24		LSB
Gain error	Internal 4.3V equivalent reference		7.14		LSB
Differential nonlinearity			> -1		LSB
Integral nonlinearity			± 4		LSB
Reference voltage	Equivalent fixed internal reference (input voltage scaling enabled). For best accuracy, the ADC conversion should be initiated through the TI-RTOS API in order to include the gain/offset compensation factors stored in FCFG1		4.3		V
Reference voltage	Fixed internal reference (input voltage scaling disabled). For best accuracy, the ADC conversion should be initiated through the TI-RTOS API in order to include the gain/offset compensation factors stored in FCFG1. This value is derived from the scaled value (4.3 V) as follows: Vref = 4.3 V × 1408 / 4095		1.48		V
Reference voltage	VDD as reference, input voltage scaling enabled		VDD		V
	VDD as reference, input voltage scaling disabled		VDD/2.82		V
Input Impedance	200 kSamples/s, voltage scaling enabled. Capacitive input,		> 1		MΩ

Parameter	Test Condition	MIN	TYP	MAX	Unit
	Input impedance depends on sampling frequency and sampling time				

For ADC characteristics or other details, please refer to CC1311R3 datasheet: CC1311R3 SimpleLink™ Arm® Cortex®-M4 Sub-1GHz wireless MCU with 352 kB flash

3.1.11. DAC Characteristics

Table 19. DAC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Resolution			8		Bits
Supply voltage	Any load, any VREF, pre-charge OFF, DAC charge-pump ON	1.8		3.8	V
	External Load, any VREF, pre-charge OFF, DAC charge-pump OFF	2.0		3.8	V
	Any load, VREF = DCOUPL, pre-charge ON	2.6		3.8	V
Clock frequency	Buffer ON (recommended for external load)	16		250	kHz
	Buffer OFF (internal load)	16		1000	kHz

For DAC characteristics or other details, please refer to CC1311R3 datasheet: CC1311R3 SimpleLink™ Arm® Cortex®-M4 Sub-1GHz wireless MCU with 352 kB flash

3.1.12. Comparator Characteristics

Tc = 25 °C, VDD = 3.0 V, unless otherwise noted.

Table 20. Continuous Time Comparator Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Input voltage range		0		VDD	V
Offset	Measured at VDD/2		± 5		mV
Decision time	Step from -10 mV to 10 mV		0.78		us
Current consumption	Internal reference		9.2		uA

3.2. RF Characteristics

The measurement is made with the evaluation module (EM board) for BDE-SG1311R3 with T_A = 25 °C, VDD = 3.0 V, DCDC enabled, GLDO disabled, unless otherwise noted.

3.2.1. 861 MHz to 1054 MHz Performance: Receiver Characteristics

Table 21. 861 MHz to 1054 MHz Performance: Receiver Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
General Parameters					
Digital channel filter programmable receive bandwidth		4		4000	kHz

Parameter	Test Condition	MIN	TYP	MAX	Unit
Data rate step size			1.5		bps
Spurious emissions 25 MHz to 1 GHz	868 MHz		< -57		dBm
Spurious emissions 1 GHz to 13 GHz			< -47		
802.15.4, 50 kbps, ±25 kHz deviation, 2-GFSK, 100 kHz RX Bandwidth					
Sensitivity	BER = 10^{-2}, 868 MHz		-110		dBm
Saturation limit	BER = 10^{-2}, 868 MHz		10		
Selectivity, ±200 kHz	BER = 10^{-2}, 868 MHz		44		dB
Selectivity, ±400 kHz			48		
Blocking, ±1 MHz			58		
Blocking, ±2 MHz			62		
Blocking, ±5 MHz			70		
Blocking, ±10 MHz			77		
Image rejection (image compensation enabled)	BER = 10^{-2}, 868 MHz		41		dB
RSSI dynamic range	Starting from the sensitivity limit		95		dB
RSSI accuracy	Starting from the sensitivity limit across the given dynamic range		± 3		dB
100 kbps, ±25 kHz deviation, 2-GFSK, 137 kHz RX Bandwidth					
Sensitivity 100 kbps	868 MHz, 1 % PER, 127 byte payload		-107.5		dBm
Selectivity, ±200 kHz	868 MHz, 1 % PER, 127 byte payload. Wanted signal at -96 dBm		31		dB
Selectivity, ±400 kHz	868 MHz, 1 % PER, 127 byte payload. Wanted signal at -96 dBm		37		
Co-channel rejection	868 MHz, 1 % PER, 127 byte payload. Wanted signal at -79 dBm		-9		
200 kbps, ± 50 kHz deviation, 2-GFSK, 311 kHz RX Bandwidth					
Sensitivity	BER = 10^{-2}, 868MHz		-105.5		dBm
Sensitivity	BER = 10^{-2}, 915MHz		-103.5		
Selectivity, ±400 kHz	BER = 10^{-2}, 915MHz. Wanted signal 3 dB above sensitivity limit.		45		dB
Selectivity, ±800 kHz			49		
Blocking, ±2 MHz			57		
Blocking, ±10 MHz			69		
500 kbps, ± 190 kHz deviation, 2-GFSK, 1150 kHz RX Bandwidth					
Sensitivity 500 kbps	915 MHz, 1% PER, 127 byte payload		-97		dBm
Selectivity, ± 1 MHz	915 MHz, 1% PER, 127 byte payload. Wanted signal at -88 dBm		14		dB
Selectivity, ± 2 MHz	915 MHz, 1% PER, 127 byte payload. Wanted signal at -88 dBm		42		dB
Co-channel rejection	915 MHz, 1% PER, 127 byte payload. Wanted signal at -71 dBm		-9		dB
1 Mbps, ± 350 kHz deviation, 2- GFSK, 1.3 MHz RX Bandwidth					
Sensitivity	BER = 10^{-2}, 868MHz		-102.5		dBm
Sensitivity	BER = 10^{-2}, 915MHz		-100.5		
Blocking, +2 MHz	BER = 10^{-2}, 915MHz. Wanted signal 3 dB above sensitivity limit.		43		dB
Blocking, -2 MHz			26		

Parameter	Test Condition	MIN	TYP	MAX	Unit
Blocking, +10 MHz			54		
Blocking, -10 MHz			48		
SimpleLink™ Long Range 2.5/5 kbps (20 ksps), 2-GFSK, ±5 kHz Deviation, FEC (Half Rate), DSSS = 1:2/1:4, 34 kHz RX Bandwidth					
Sensitivity	2.5 kbps, BER = 10^{-2}, 868MHz		-120		dBm
Sensitivity	5 kbps, BER = 10^{-2}, 868MHz		-118		dBm
Saturation limit	2.5 kbps, BER = 10^{-2}, 868MHz		10		dBm
Selectivity, ±100 kHz	2.5 kbps, BER = 10^{-2}, 868MHz		49		dB
Selectivity, ±200 kHz			50		
Selectivity, ±300 kHz			51		
Blocking, ±1 MHz	2.5 kbps, BER = 10^{-2}, 868MHz		63		dB
Blocking, ±2 MHz			69		
Blocking, ±5 MHz			79		
Blocking, ±10 MHz			88		
Image rejection (image compensation enabled)	2.5 kbps, BER = 10^{-2}, 868MHz		47		dB
RSSI dynamic range	Starting from the sensitivity limit		97		dB
RSSI accuracy	Starting from the sensitivity limit across the given dynamic range		± 3		dB
Narrowband, 9.6 kbps ± 2.4 kHz deviation, 2-GFSK, 17.1 kHz RX Bandwidth					
Sensitivity	1% BER, 868MHz		-121.5		dBm
Adjacent Channel Rejection	1% BER, 868MHz. Wanted signal 3 dB above usable sensitivity limit (usable sensitivity -104.6dBm). Interferer ± 20 kHz		41		dB
Alternate Channel Rejection	1% BER, 868MHz. Wanted signal 3 dB above usable sensitivity limit (usable sensitivity -104.6dBm). Interferer ± 40 kHz		42		dB
Blocking, ± 1 MHz	1% BER, 868MHz. Wanted signal 3 dB above usable sensitivity limit (usable sensitivity -104.6dBm).		65		dB
Blocking, ± 2 MHz	1% BER, 868MHz. Wanted signal 3 dB above usable sensitivity limit (usable sensitivity -104.6dBm).		70		dB
Blocking, ± 10 MHz	1% BER, 868MHz. Wanted signal 3 dB above usable sensitivity limit (usable sensitivity -104.6dBm).		85		dB
Wi-SUN, 2-GFSK					
Sensitivity	50 kbps, ±12.5 kHz deviation, 2-GFSK, 868 MHz, 68 kHz RX BW, 10% PER, 250 byte payload		-111.5		dBm
Selectivity, ± 100 kHz, 50 kbps, ± 12.5 kHz deviation, 2-GFSK, 868.3 MHz	50 kbps, ±12.5 kHz deviation, 2-GFSK, 68 kHz RX Bandwidth, 868.3 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		30		dB
Selectivity, ± 200 kHz, 50 kbps, ± 12.5 kHz deviation, 2-GFSK, 868.3 MHz	50 kbps, ±12.5 kHz deviation, 2-GFSK, 68 kHz RX Bandwidth, 868.3 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		36		dB
Sensitivity	50 kbps, ±25 kHz deviation, 2-GFSK, 918.2 MHz, 98 kHz RX BW, 10% PER, 250 byte payload		-107.5		dBm
Selectivity, ± 200 kHz, 50 kbps, ± 25 kHz deviation, 2-GFSK, 918.2 MHz	50 kbps, ±25 kHz deviation, 2-GFSK, 98 kHz RX Bandwidth, 918.2 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		34		dB

Parameter	Test Condition	MIN	TYP	MAX	Unit
Selectivity, ± 400 kHz, 50 kbps, ± 25 kHz deviation, 2-GFSK, 918.2 MHz	50 kbps, ±25 kHz deviation, 2-GFSK, 98 kHz RX Bandwidth, 918.2 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		41		dB
Sensitivity	100 kbps, ±25 kHz deviation, 2-GFSK, 868 MHz, 135 kHz RX BW, 10% PER, 250 byte payload		-107.5		dBm
Selectivity, ± 200 kHz, 100 kbps, ± 25 kHz deviation, 2-GFSK, 868.3 MHz	100 kbps, ±25 kHz deviation, 2-GFSK, 135 kHz RX Bandwidth, 868.3 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		37		dB
Selectivity, ± 400 kHz, 100 kbps, ± 25 kHz deviation, 2-GFSK, 868.3 MHz	100 kbps, ±25 kHz deviation, 2-GFSK, 135 kHz RX Bandwidth, 868.3 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		45		dB
Sensitivity	100 kbps, ±50 kHz deviation, 2-GFSK, 920.9 MHz, 196 kHz RX BW, 10% PER, 250 byte payload		-104.5		dBm
Selectivity, ± 400 kHz, 100 kbps, ± 50 kHz deviation, 2-GFSK, 920.9 MHz	100 kbps, ±50 kHz deviation, 2-GFSK, 196 kHz RX Bandwidth, 920.9 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		40		dB
Selectivity, ± 800 kHz, 100 kbps, ± 50 kHz deviation, 2-GFSK, 920.9 MHz	100 kbps, ±50 kHz deviation, 2-GFSK, 196 kHz RX Bandwidth, 920.9 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		49		dB
Sensitivity	150 kbps, ±37.5 kHz deviation, 2-GFSK, 920.9 MHz, 273 kHz RX BW, 10% PER, 250 byte payload		-104.5		dBm
Selectivity, ± 400 kHz, 150 kbps, ± 37.5 kHz deviation, 2-GFSK, 920.9 MHz	150 kbps, ±37.5 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 920.9 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		41		dB
Selectivity, ± 800 kHz, 150 kbps, ± 37.5 kHz deviation, 2-GFSK, 920.9 MHz	150 kbps, ±37.5 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 920.9 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		47		dB
Sensitivity	200 kbps, ±50 kHz deviation, 2-GFSK, 918.4 MHz, 273 kHz RX BW, 10% PER, 250 byte payload		-102.5		dBm
Selectivity, ± 400 kHz, 200 kbps, ± 50 kHz deviation, 2-GFSK, 918.4 MHz	200 kbps, ±50 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 918.4 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		42		dB
Selectivity, ± 800 kHz, 200 kbps, ± 50 kHz deviation, 2-GFSK, 918.4 MHz	200 kbps, ±50 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 918.4 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		49		dB
Sensitivity	200 kbps, ±100 kHz deviation, 2-GFSK, 920.8 MHz, 273 kHz RX BW, 10% PER, 250 byte payload		-101.5		dBm
Selectivity, ± 600 kHz, 200 kbps, ± 100 kHz deviation, 2-GFSK, 920.8 MHz	200 kbps, ±100 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 920.8 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		45		dB
Selectivity, ± 1200 kHz, 200 kbps, ± 100 kHz deviation, 2-GFSK, 920.8 MHz	200 kbps, ±100 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth, 920.8 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		52		dB
Sensitivity	300 kbps, ±75 kHz deviation, 2-GFSK, 917.6 MHz, 498 kHz RX		-101		dBm

Parameter	Test Condition	MIN	TYP	MAX	Unit
	BW, 10% PER, 250 byte payload				
Selectivity, ± 600 kHz, 300 kbps, ± 75 kHz deviation, 2-GFSK, 917.6 MHz	300 kbps, ±75 kHz deviation, 2-GFSK, 498 kHz RX Bandwidth, 917.6 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		42		dB
Selectivity, ± 1200 kHz, 300 kbps, ± 75 kHz deviation, 2-GFSK, 917.6 MHz	300 kbps, ±75 kHz deviation, 2-GFSK, 498 kHz RX Bandwidth, 917.6 MHz, 10% PER, 250 byte payload. Wanted signal 3 dB above sensitivity level		47		dB

3.2.2. 861 MHz to 1054 MHz Performance: Transmitter Characteristics

Table 22. 861 MHz to 1054 MHz Performance: Transmitter Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
General Parameters					
Max output power, boost mode	Minimum supply voltage (VDD) for boost mode is 2.1V, 868 MHz and 915 MHz		13.1		dBm
12.5dBm setting	868MHz and 915MHz		11.6		dBm
12dBm setting	868MHz and 915MHz		11.2		dBm
11dBm setting	868MHz and 915MHz		10.3		dBm
10dBm setting	868MHz and 915MHz		9.5		dBm
9dBm setting	868MHz and 915MHz		8.5		dBm
8dBm setting	868MHz and 915MHz		7.9		dBm
7dBm setting	868MHz and 915MHz		7.0		dBm
6dBm setting	868MHz and 915MHz		6.0		dBm
5dBm setting	868MHz and 915MHz		4.6		dBm
4dBm setting	868MHz and 915MHz		4.1		dBm
3dBm setting	868MHz and 915MHz		3.2		dBm
2dBm setting	868MHz and 915MHz		2.5		dBm
1dBm setting	868MHz and 915MHz		1.4		dBm
0dBm setting	868MHz and 915MHz		0.5		dBm
Output power programmable range	868 MHz and 915 MHz		24		dB
Output power variation over temperature	+10 dBm setting Over recommended temperature operating range		± 2		dB
Output power variation over temperature Boost mode	+14 dBm setting Over recommended temperature operating range		± 1.5		dB

3.2.3. 359 MHz to 527 MHz Performance: Receiver Characteristics

Table 23. 359 MHz to 527 MHz Performance: Receiver Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
General Parameters					
Spurious emissions 25 MHz to 1 GHz	433.92 MHz		< -57		dBm

Parameter	Test Condition	MIN	TYP	MAX	Unit
Spurious emissions 1 GHz to 13 GHz			< -47		
IEEE 802.15.4, 50 kbps, ±25 kHz deviation, 2-GFSK, 78 kHz RX Bandwidth					
Sensitivity	BER = 10^{-2}, 433.92 MHz		-110		dBm
Saturation limit	BER = 10^{-2}, 433.92 MHz		10		dBm
Selectivity, +200 kHz	BER = 10^{-2}, 433.92 MHz		48		dB
Selectivity, -200 kHz			43		
Selectivity, +400 kHz			53		
Selectivity, -400 kHz			44		
Blocking, +1 MHz			60		
Blocking, -1 MHz			54		
Blocking, +2 MHz			62		
Blocking, -2 MHz			61		
Blocking, +10 MHz			75		
Blocking, -10 MHz			75		
Image rejection (image compensation enabled)	BER = 10^{-2}, 433.92 MHz		44		dB
RSSI dynamic range	Starting from the sensitivity limit		95		dB
RSSI accuracy	Starting from the sensitivity limit across the given dynamic range		± 3		dB
200 kbps, ± 50 kHz deviation, 2-GFSK, 273 kHz RX Bandwidth					
Sensitivity	BER = 10^{-2}, 433.92 MHz		-104		dBm
Saturation limit	BER = 10^{-2}, 433.92 MHz		10		dBm
Selectivity, ±400 kHz	BER = 10^{-2}, 433.92 MHz		48		dB
Blocking, ±1 MHz			52		
Blocking, ±2 MHz			55		
Blocking, ±10 MHz			68		
Image rejection (image compensation enabled)	BER = 10^{-2}, 433.92 MHz		45		dB
RSSI dynamic range	Starting from the sensitivity limit		89		dB
RSSI accuracy	Starting from the sensitivity limit across the given dynamic range		± 3		dB
SimpleLink™ Long Range 2.5/5 kbps (20 ksps), ±5 kHz Deviation, 2-GFSK, 34 kHz RX Bandwidth, FEC = 1:2, DSSS = 1:2/1:4					
Sensitivity	2.5 kbps, BER = 10^{-2}, 433.92MHz		-121		dBm
Sensitivity	5 kbps, BER = 10^{-2}, 433.92MHz		-119		dBm
Saturation limit	5 kbps, BER = 10^{-2}, 433.92MHz		10		dBm
Selectivity, +100 kHz	5 kbps, BER = 10^{-2}, 433.92MHz		55		dB
Selectivity, -100 kHz			53		
Blocking, +1 MHz	5 kbps, BER = 10^{-2}, 433.92MHz		69		dB
Blocking, -1 MHz			65		
Blocking, +2 MHz			71		
Blocking, -2 MHz			70		
Blocking, +10 MHz			84		
Blocking, -10 MHz			84		
Image rejection (image compensation enabled)	5 kbps, BER = 10^{-2}, 433.92MHz		49		dB

Parameter	Test Condition	MIN	TYP	MAX	Unit
RSSI dynamic range	Starting from the sensitivity limit		101		dB
RSSI accuracy	Starting from the sensitivity limit across the given dynamic range		± 3		dB

3.3. Antenna Characteristics

Refer to Section 7.1.1 for certified antenna list.

4. Mechanical Specifications

4.1. Dimensions

The following pages include mechanical, footprint drawings, and marking information.

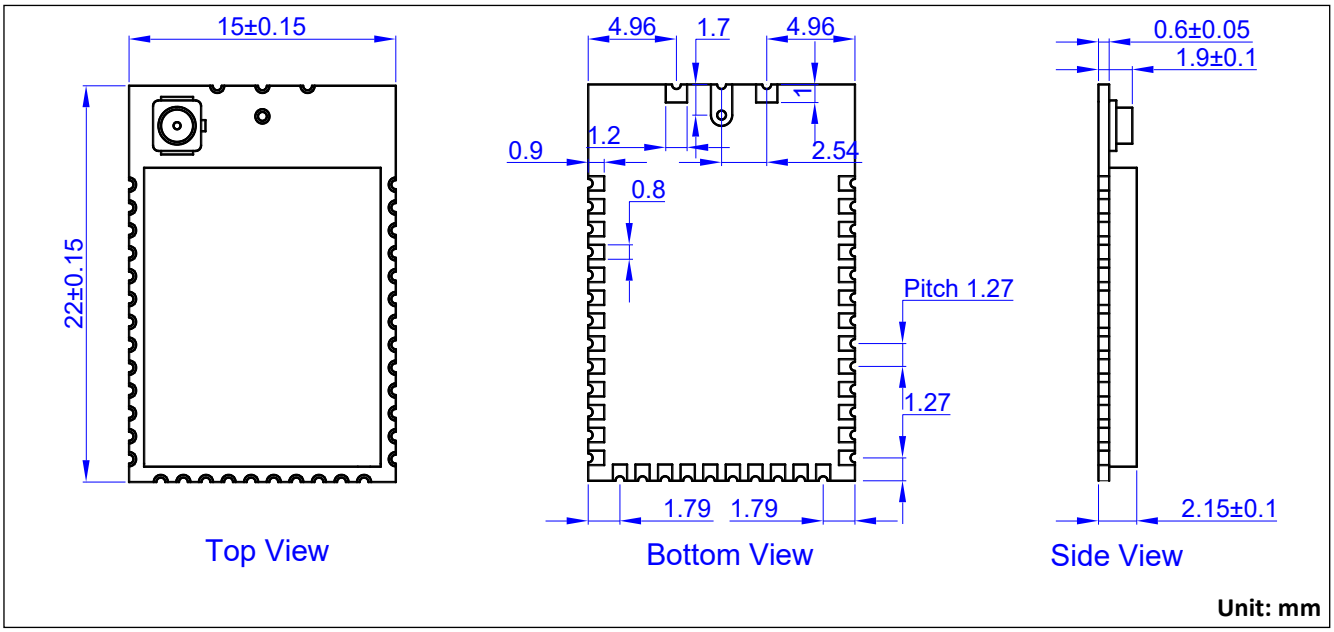


Figure 5. Mechanical Drawing of BDE-SG1311R3

4.2. PCB Footprints

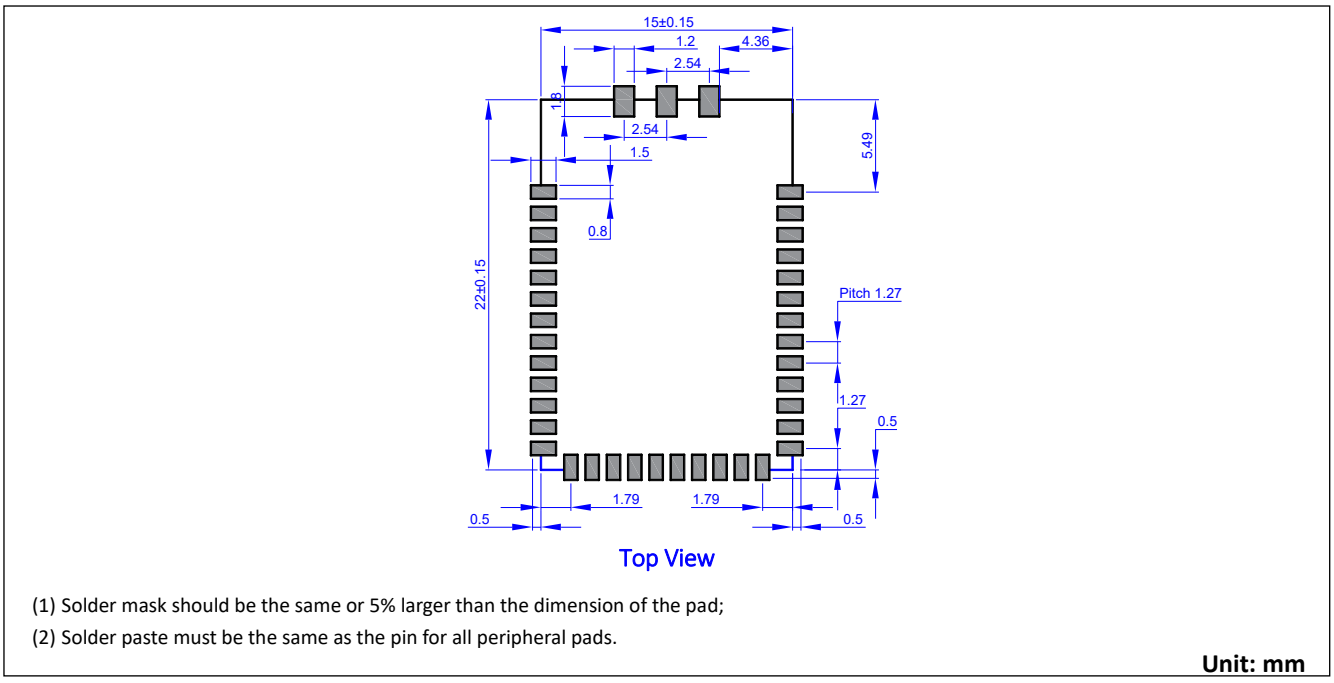
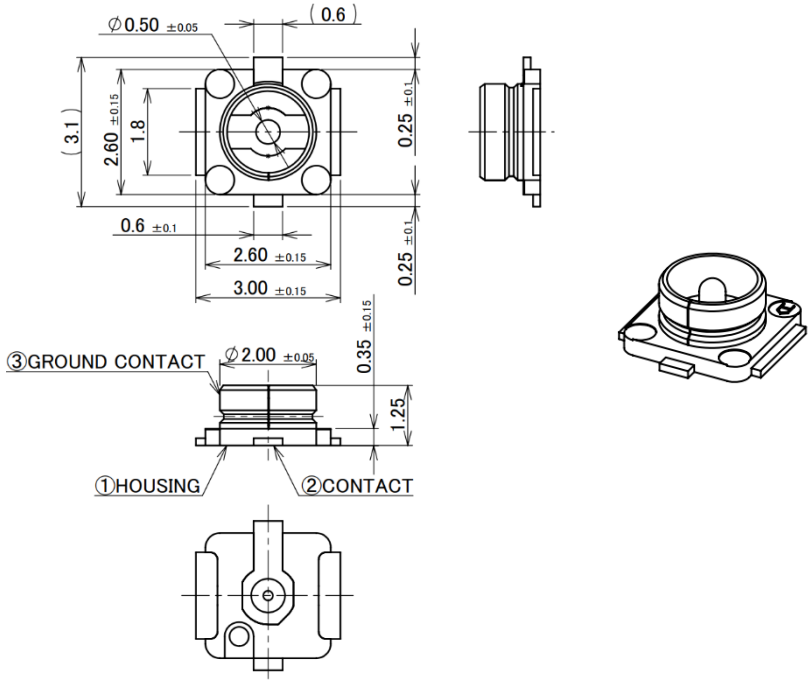


Figure 6. Recommended Module Footprint of BDE-SG1311R3

4.3. U.FL Connector Specification

The drawing and specification of the U.FL connector utilized in the module is as below for reference.

The dimension unit in below drawing is millimeter.



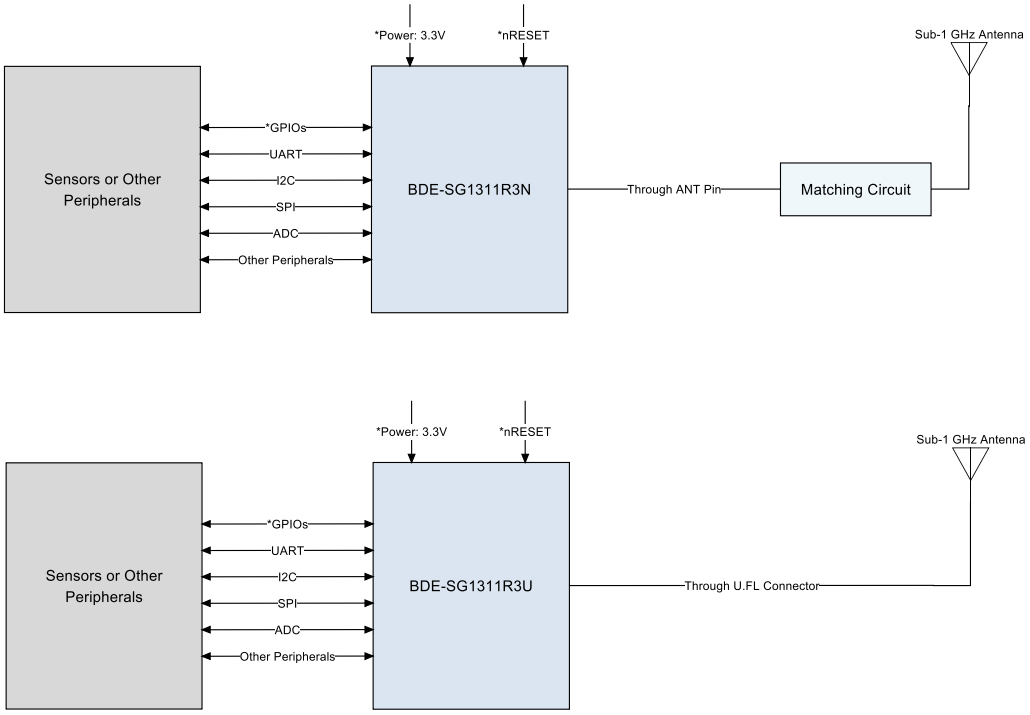
RATING VOLTAGE	60 V AC (R.M.S)	
RATING FREQUENCY	DC～9GHz	
OPERATING TEMPERATURE	233～363K (−40℃～+90℃)	
VSWR	RECEPTACLE: 1.3 MAX. AT 0.1～3 GHz, 1.4 MAX. AT 3～6 GHz, 1.8 MAX. AT 6～9 GHz	
MAIN CONTACT RESISTANCE	INITIAL: 20 mohm MAX. / AFTER TEST: ⊿R 20 mohm MAX.	
GROUND CONTACT RESISTANCE	INITIAL: 20 mohm MAX. / AFTER TEST: ⊿R 100 mohm MAX.	
INSULATION RESISTANCE	INITIAL: 500 Mohm MIN. / AFTER TEST: 100 Mohm MIN.	
DIELECTRIC WITHSTANDING VOLTAGE	200 V AC, 1 MINUTE	
DURABILITY	30 CYCLES	
UNMATING FORCE (INITIAL / AFTER TEST)	INITIAL: 5 N MIN. AFTER TEST: 3 N MIN.	INITIAL: 4 N MIN. AFTER TEST: 2 N MIN.

Figure 7. U.FL Connector Drawing and Specification

5. Integration Guideline

5.1. System Diagram

Below block diagram is applicable when the module is used as a SoC running the application and the protocol stack in the system CPU inside the module.



(1) The module has already been implemented with required decoupling capacitors, therefore, external decoupling capacitors are not needed. However, proper decoupling capacitors can also be added to increase module power stability depending on customer's application;
(2) The module has the internal reset circuit on board, e.g. a 100K ohm pull-up resistors and a 0.1uF decouple capacitor. Therefore, external reset circuit is not needed for the same purpose;
(3) If the SPI flash variants is chosen, please do not utilize these four GPIOs in your design, because they are already assigned to the on-board SPI flash. They are GPIO_8, GPIO_9, GPIO_10 and GPIO_20;
(4) It is recommended to reserve the matching circuit for antenna for tuning if the ANT pin version is chosen.

Figure 8. High-Level System Block Diagram

5.2. Module Placement

The placement of the module in the base board is critical in your design. Improper placement can lead to poor antenna performance. BDE recommend following below recommended placement in your design.

Any form of proximity to the metal or other material will change/degrade the antenna performance. Keep the antenna area as far as possible to the metal material in any direction.

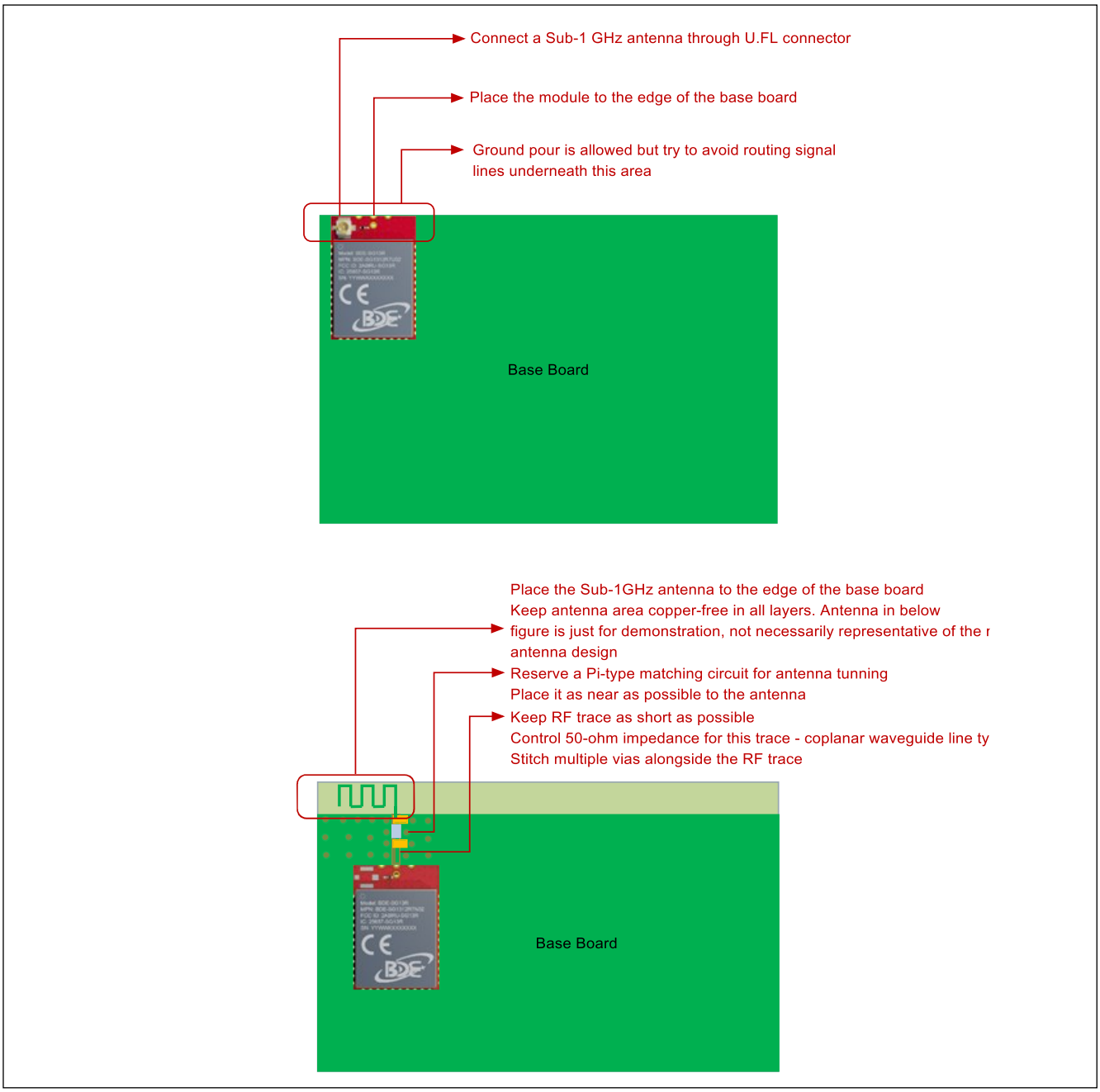


Figure 9. Module Placement Recommendations

5.3. Other Design Considerations

Table 24. Other Design Considerations

Thermal	
1	The proximity of ground vias must be close to each ground pad of the module.
2	Signal traces must not be run underneath the module on the layer where the module is mounted.
3	Have a complete ground pour in layer 2 for thermal dissipation.
4	Have a solid ground plane and ground vias under the module for stable system and thermal dissipation.
5	Increase the ground pour in the first layer and have all of the traces from the first layer on the inner layers, if possible.
6	Signal traces can be run on a third layer under the solid ground layer, which is below the module mounting layer.

RF Trace and Antenna Routing	
7	The RF trace antenna feed must be as short as possible beyond the ground reference. At this point, the trace starts to radiate.
8	The RF trace bends must be gradual with an approximate maximum bend of 45° with trace mitered. RF traces must not have sharp corners.
9	RF traces must have via stitching on the ground plane beside the RF trace on both sides.
10	RF traces must have constant impedance (50-ohm Coplanar or microstrip transmission line).
11	For best results, the RF trace ground layer must be the ground layer immediately below the RF trace. The ground layer must be solid.
12	There must be no traces or ground under the antenna section.
13	RF traces must be as short as possible. The antenna, RF traces, and modules must be on the edge of the PCB product. The proximity of the antenna to the enclosure and the enclosure material must also be considered.
14	BDE recommends using double-shielded coaxial RF cable to connect with the U.FL connector with antenna if the U.FL variants are selected.
15	Do not place or run the RF cable right above or below the module.
16	If there are some other radios besides this module in the system, try to place them apart as far as possible. And ensure there is at least 25 dB isolation between the antenna port of every radio.
Supply and Interface	
17	Make VDD traces as wide as possible to ensure reduced inductance and trace resistance.
18	If possible, shield VDD traces with ground above, below, and beside the traces.

5.4. Development Resources

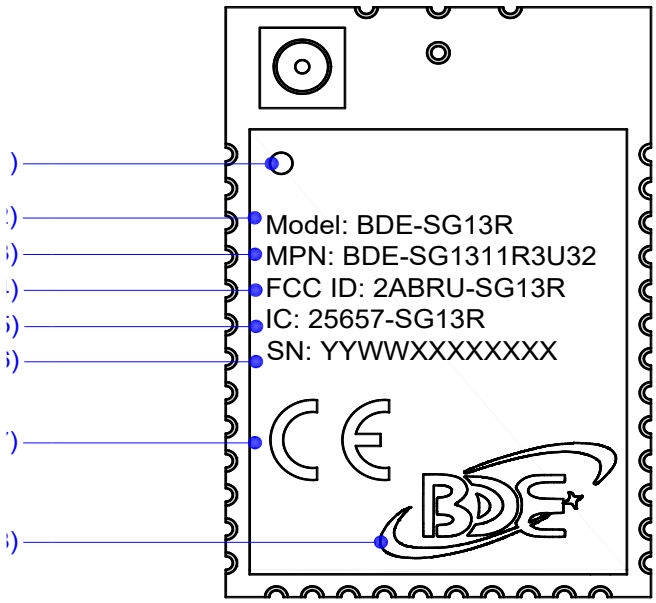
For more information on the EVK, please visit the product page of the module on bdecomm.com.

6. Handling Instructions

The module is the surface mount module with LCC-39 footprint. It is designed to conform to the major manufacturing guidelines, including the commercial, industrial manufacturing process.

In this section, we will cover the basic shipping information, including the module markings, packaging, labeling, ect. And also, the instructions on how to handle the module in terms of storage, assembly and so on.

6.1. Module Marking

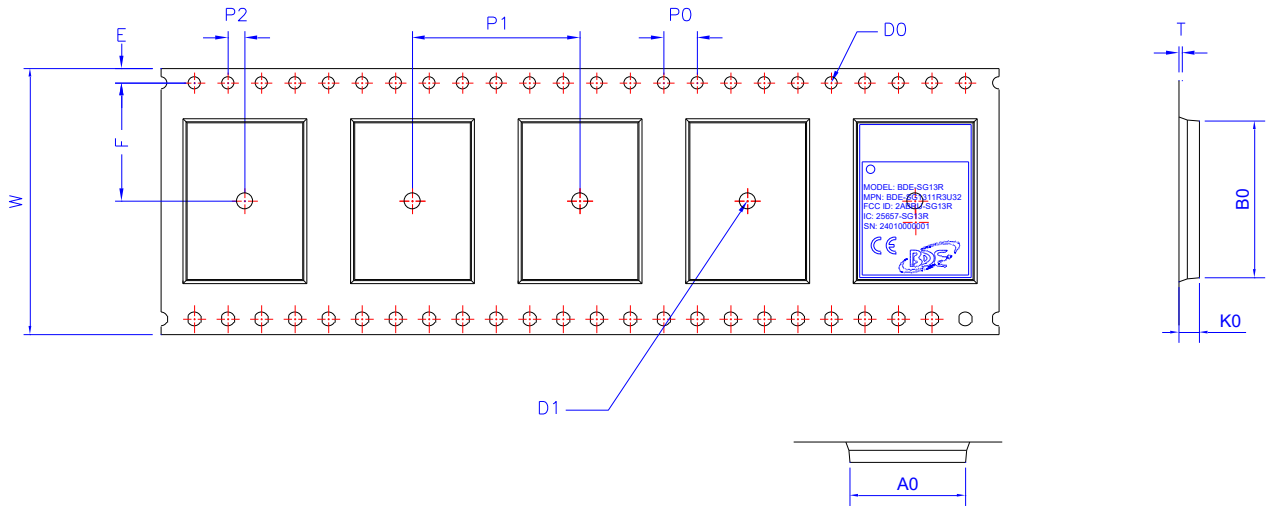


(1) Pin one index;
(2) Model series number;
(3) Orderable manufacturer part number. Refer to Table 1;
(4) FCC ID;
(5) IC ID;
(6) Serial number for traceability;
(7) CE mark;
(8) BDE logo

Figure 10. Module Marking

6.2. Packaging Information

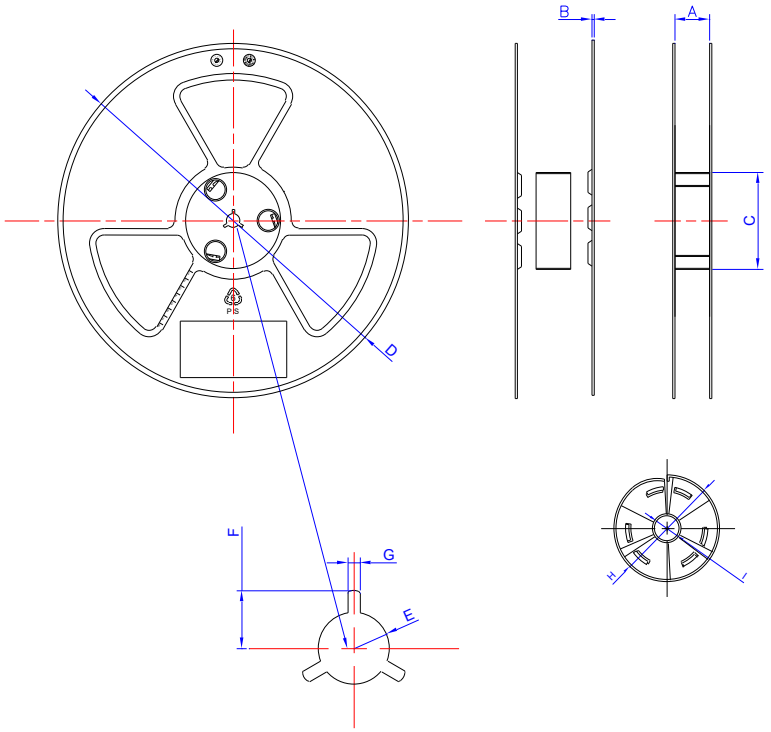
6.2.1. Tape and Reel Package Information



W	A_0	B_0	K_0	P_1	F	E	D_0	D_1	P_0	P_2	T
$44.00^{+0.30}_{-0.10}$	$15.35^{+0.10}_{-0.10}$	$22.45^{+0.10}_{-0.10}$	$2.50^{+0.10}_{-0.10}$	$20.00^{+0.10}_{-0.10}$	$20.20^{+0.10}_{-0.10}$	$1.75^{+0.10}_{-0.10}$	$1.50^{+0.10}_{-0.00}$	$2.00^{+0.10}_{-0.00}$	$4.00^{+0.10}_{-0.10}$	$2.00^{+0.10}_{-0.10}$	$0.35^{+0.05}_{-0.05}$

(1) Cumulative tolerance for every 10 sprockets pitch is ±0.2mm;
(2) Carrier camber not to exceed 1mm in every 100mm;
(3) All dimensions are in millimeter and meets EIA-481-C requirements;
(4) Material: PS Black polystyrene;
(5) Thickness: 0.35±0.05mm;
(6) Packing length per 13"reel: 20.7 meters;
(7) Component load per 13"reel: 1000+30pcs (15 voids each to the head and tail);
(8) RoHS compliance;
(9) Anti-static coefficient of $10^{6\text{-}11}\Omega$.

Figure 11. Carrier Tape Drawing for BDE-SG1311R3 variants



A	B	C	D	E	F	G	H	I
44	2	100	330	6.75	10.85	2.5	100	24

(1) All dimensions are in millimeter;
(2) Material: PS blue polystyrene;

Figure 12. 13-INnch Reel Drawing

6.2.2. Carton Information and Labeling

6.2.2.1. Carton Information

Figure 13. Carton Information

6.2.2.2. Reel Label

The reel label will be affixed onto the reel, Anti-ESD bag and reel box. It mainly shows the MPN (Manufacturer Part Number), CPN (Customer Part Number), PO (Purchase Order Number), LOT number, QTY (Quantity), DC (Date Code) and MSL (Moisture

Sensitivity Level). Sometimes, it also shows other information, such as the regulatory information.

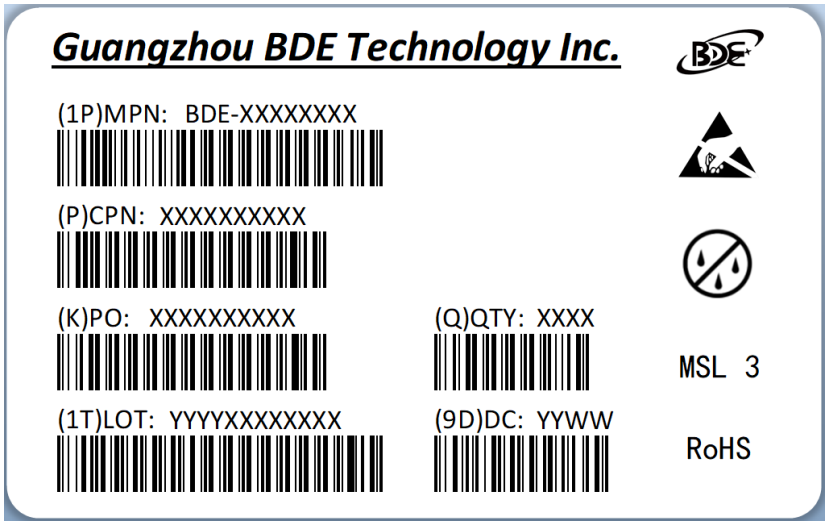


Figure 14. Reel Label Information

6.2.2.3. Carton Label

The carton label will be affixed onto the surface of the carton. If the carton contains different Part Numbers or POs, there will be different labels representing different Part Numbers, different Pos and Quantity.

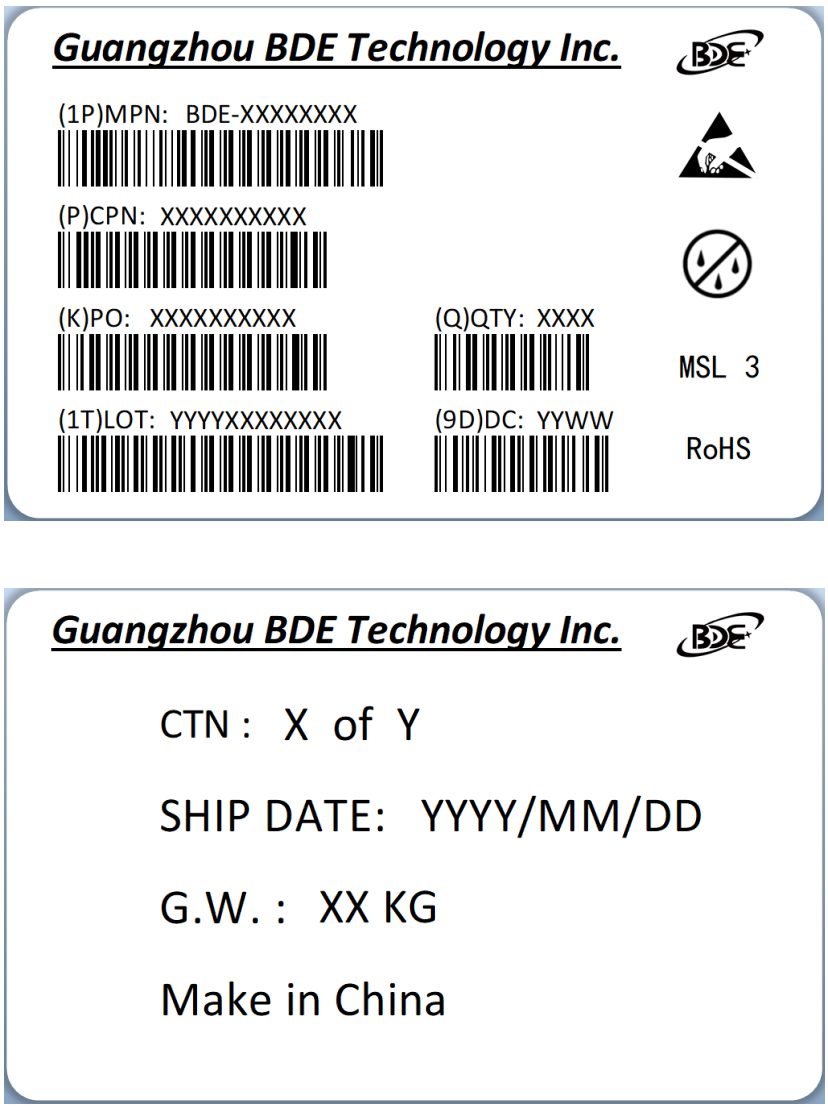


Figure 15. Carton Label Information

6.3. Assembly Instruction

6.3.1. Moisture Sensitive Level

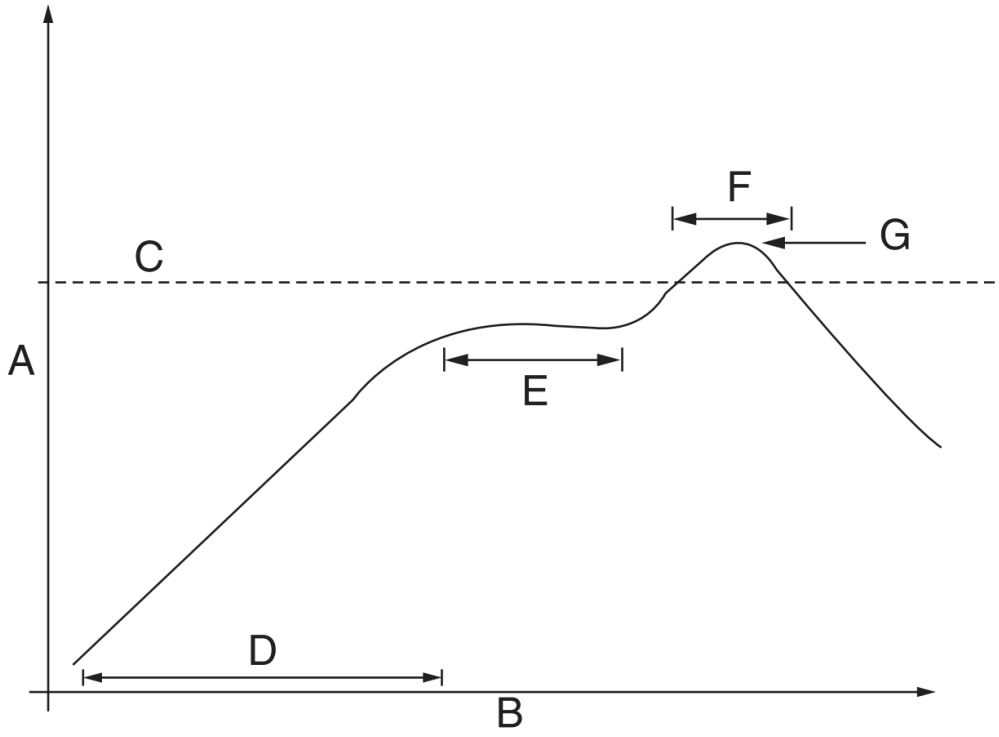
The MSL (Moisture Sensitive Level) of the module is MSL-3. Handling guidelines are listed as below:

(1) The floor life for MSL-3 device is 168 hours in ambient environment 30°C/60%RH. Before assembly, make sure to check if the modules are packaged with desiccate and humidity indicator card;

(2) After the bag is opened, make sure to mount the modules within 168 hours at factory conditions (< 30°C/60% RH) or stored at <10% RH. Repackage is needed with new desiccate and humidity indicator card if the modules are not mounted before exceeding floor life;

(3) If the card reads >10%, or the modules have been exposed for over 168 hours, the modules need to be baked before mounted. Recommended baking condition is 125℃ for 8 hours.

6.3.2. Reflow Profile



(1) A – Temperature
(2) B – Time
(3) C – Alloy liquidus temperature
(4) D – Preheat slope = temperature ramp rate
(5) E – Preheat dwell = soak time
(6) F – Time above liquidus
(7) G – Peak temperature = maximum assembly temperature

Figure 16. Thermal Profile Schematic

Table 25. Reflow Profile Parameters [(1)] [(3)]

Item	Temperature Range	Ramp Rate / Time
D, preheat zone	30°C ~ 175°C	2°C ~ 4°C per second
E, soak zone	150°C ~ 200°C	60 ~ 120 seconds
C, Alloy liquidus temperature	217°C ~ 220°C	-
F, reflow zone	230°C ~ 245°C	60 ~ 90 seconds
G, target maximum reflow temperature	250°C	-
Absolute peak temperature [(2)]	260°C	-

(1) This is for Pb-free (SAC 305) paste. Different pastes require different profiles for optimum performance, so it is important to consult the paste manufacturer before developing the solder profile;
(2) Exceed the absolute peak temperature for certain period, e.g. 20s might damage the device or affect the reliability;
(3) It is recommended that the modules do not go through the reflow process more than one time.

6.3.3. Other Consideration

(1) Ultrasonic cleaning process is discouraged for the modules as the process might damage the module permanently, especially for the crystal oscillator in the module.
(2) Conformal coating is not allowed to this module. It will impact the reliability of the module once the coating flooded into the shield.

7. Certification

7.1. Regulatory Compliance

The module is certified for FCC, IC/ISED and ETSI/CE as listed in below table. More regions can be cover by request.

Table 26. Certification Information

Regulatory Body / Region	Standard	ID	MPN
FCC (USA)	FCC CFR 47 PART 15 C (15.247)	2ABRU-SG13R	BDE-SG1311R3U32 BDE-SG1311R3N32 BDE-SG1311R3U0 BDE-SG1311R3N0 BDE-SG1311R3U32-IN BDE-SG1311R3N32-IN BDE-SG1311R3U0-IN BDE-SG1311R3N0-IN
IC/ISED (Canada)	RSS-247 Issue 3 RSS-Gen Issue 5 ANSI C63.10: 2013	25657-SG13R	
ETSI/CE (Europe)	ETSI EN 301 489-1 V2.2.3 (2019-11) ETSI EN 301 489-3 V2.3.2 (2023-01) EN 55032:2015/A11:2020 EN 55035:2017/A11:2020 ETSI EN 300 220-1 V3.1.1 (2017-02) ETSI EN 300 220-2 V3.2.1 (2018-06) EN IEC 62311:2020 EN IEC 62368-1:2020+A11:2020	NA	

7.1.1. Certified Antennas

The module series has been tested and certified with one antenna, and the BDE-SG1311R3U and BDE-SG1311R3N variants utilize an external Sub-1GHz whip antenna.

The characteristic of the antenna is listed in below.

Table 27. Certified Antenna List

Antenna Type	Manufacturer	MPN	Peak Gain (dBi)	Note
Whip antenna	BDE	BDE-W89-20713-HRP	3.8	External

Customers are encouraged to use the certified antennas in the case of external antenna options to reduce certification testing effort and risk of failing. If customer want to choose another antenna that fits their product, there are some scenarios that need to be considered.

If the external antenna is of the same antenna type and of equal or less gain compared to the ones listed in above table, and with similar in-band and out-of-band characteristic, then the antenna can be used with the module in USA and Canada where modular approval is applicable, as long as the spot-check testing of the new antenna with host is performed to verified that it will not change the performance. However, in countries such as EU countries applying the ETSI standards where the modular approval is not applicable, the radiated emissions are always tested with the end product with any antennas.

If the external antenna is of a different type or with non-similar in-band and out-of-band characteristic, but still has equal gain or less gain compared to the above listed antennas. The new antenna can be added to the existing modular grant/certificate by filing a permissive change, C2PC (Class II Permissive Change) in case of FCC and ISED. The radiated emission testing is needed, but re-certification is not required.

In the case of the external antenna with higher gain than the peak gain listed in above table are very likely to require a full new end product certification. However, we recommended that you consult with your certification house to understand the correct approaches for your product case by case.

7.1.2. FCC Compliance

7.1.2.1. FCC Statement

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions:

(1) This device may not cause harmful interference, and,

(2) This device must accept any interference received, including interference that may cause undesired operation.

7.1.2.2. FCC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.1.2.3. Integration Instructions

List of applicable FCC rules

FCC Part 15.247

Specific operational use conditions

This transmitter/module and its antenna(s) must not be co-located or operating in conjunction with any transmitter. This information also extends to the host manufacturer's instruction manual.

Limited module procedures

Not applicable

Trace antenna designs

Not applicable

RF exposure considerations

This equipment complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This compliance to FCC radiation exposure limits for an uncontrolled environment, and minimum of 20cm separation between antenna and body. The host product manufacturer would provide the above information to end users in their end-product manuals.

Antennas

Refer to Table 27

Label and compliance information

The end product must carry a physical label or shall use e-labeling followed KDB784748D01 and KDB784748 stating "Contains Transmitter Module FCC ID: 2ABRU-SG13R".

Information on test modes and additional testing requirements

Contact BDE for more information.

Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for the specific rule parts (FCC Part 15.247) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed when contains digital circuity.

(OEM) Integrator has to assure compliance of the entire end-product that includes the module. For 15 B (§15.107 and if applicable §15.109) compliance, the host manufacturer is required to show compliance with 15 while the module is installed and operating.

Furthermore, the module should be transmitting and the evaluation should confirm that the module's intentional emissions (15C) are compliant (fundamental / out-of-band). Finally, the integrator has to apply the appropriate equipment authorization (e.g. Verification) for the new host device per definition in §15.101. Integrator is reminded to assure that these installation instructions will not be made available to the end-user of the final host device.

7.1.3. IC/ISED Compliance

7.1.3.1. IC Statement

This device contains license-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's license-exempt RSS(s). Operation is subject to the following two conditions:

(1) This device may not cause interference, and,

(2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licencecontenudans le présentappareilestconforme aux CNR d'Innovation, Sciences et Développementéconomique Canada applicables aux appareils radio exempts de licence. L'exploitationestautorisée aux deux conditions suivantes :

(1) L' appareil ne doit pas produire de brouillage;

(2) L' appareildoit accepter tout brouillageradioélectriquesubi, mêmesi le brouillageest susceptible d' encompromettre le fonctionnement.

7.1.3.2. IC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.1.3.3. Integration Instructions

Label and compliance information

The final host device, into which this RF module is integrated has to be labeled with an auxiliary label stating the IC of the RF module, such as "Contains transmitter module IC: 25657-SG13R".

Informations sur l'étiquette et la conformité

Le périphériquehôte final, danslequelce module RF estintégré "doitêtreétiqueté avec uneétiquetteauxiliaireindiquant le CI du module RF, tel que "Contient le module émetteur IC: 25657-SG13R".

Radio Frequency Exposure Statement for IC

The device has been evaluated to meet general RF exposure requirements. The device can be used in mobile exposure conditions. The min separation distance is 20cm.

Déclaration d'exposition aux radiofréquences pour IC

L'appareil a été évalué pour répondre aux exigences générales en matière d'exposition aux RF. L'appareil peut être utilisé dans des conditions d'exposition mobiles. La distance de séparation minimale est de 20 cm. (TBD)

This radio transmitter [IC: 25657-SG13R] has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed in Table 27, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Cet émetteur radio [IC: 25657-SG13R] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous, avec le gain maximal admissible indiqué. Les types d'antenne non inclus dans cette liste qui ont un gain supérieur au gain maximum indiqué pour tout type répertorié sont strictement interdits pour une utilisation avec cet appareil.

7.1.3.4. ETSI/CE Compliance

The module is certified with required EU radio and EMC directives. See Table 26 for detailed standards the module complies with.

8. Ordering Information

Table 28. Ordering Information

Part Number	Description	Size (mm)	Shipping Form	MOQ
BDE-SG1311R3U32	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with U.FL connector, with On-board 32Mbit SPI Flash, -40℃ to +85℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3N32	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with ANT pin, with On-board 32Mbit SPI Flash, -40℃ to +85℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3U0	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with U.FL connector, without On-board 32Mbit SPI Flash, -40℃ to +85℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3N0	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with ANT pin, without On-board 32Mbit SPI Flash, -40℃ to +85℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3U32-IN	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with U.FL connector, with On-board 32Mbit SPI Flash, -40℃ to +105℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3N32-IN	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with ANT pin, with On-board 32Mbit SPI Flash, -40℃ to +105℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3U0-IN	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with U.FL connector, without On-board 32Mbit SPI Flash, -40℃ to +105℃	22 × 15 × 2.15	Tape & Reel	1K
BDE-SG1311R3N0-IN	BDE multi-protocol Sub-1GHz wireless module based on CC1311R31T0RGZR, with ANT pin, without On-board 32Mbit SPI Flash, -40℃ to +105℃	22 × 15 × 2.15	Tape & Reel	1K

9. Revision History

Revision	Date	Description
V0.1	5-November-2024	Preliminary, draft
V1.0	21-February-2025	Production version

Important Notice and Disclaimer

The information contained herein is believed to be reliable. BDE makes no warranties regarding the information contain herein. BDE assumes no responsibility or liability whatsoever for any of the information contained herein. BDE assumes no responsibility or liability whatsoever for the use of the information contained herein. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the user. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for BDE products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information.

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